


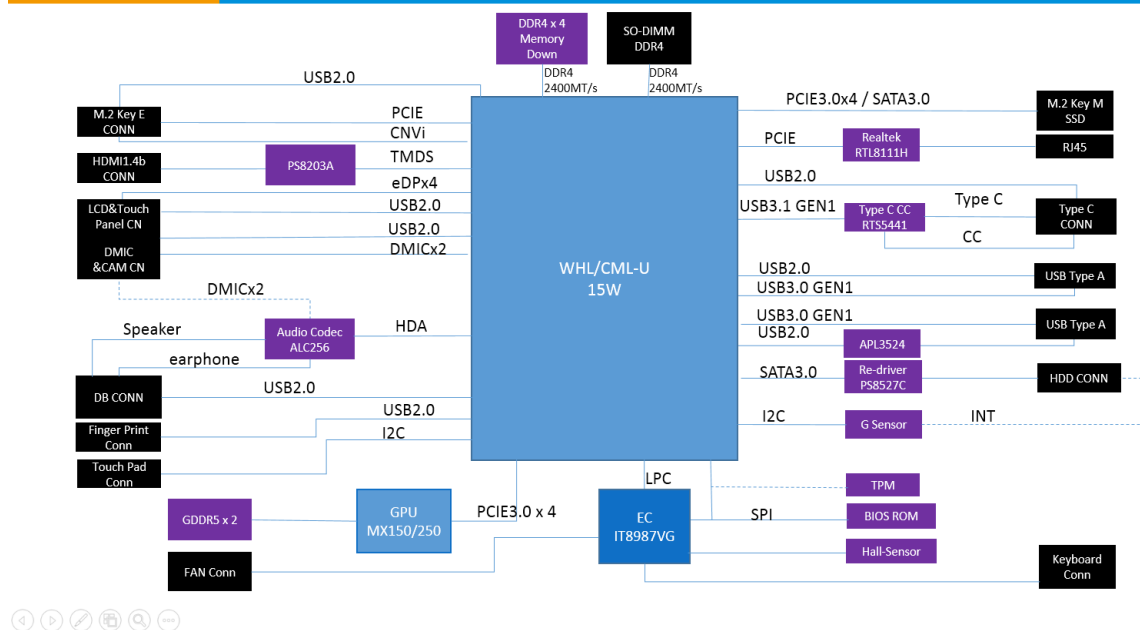
# HuaQin Confidential

## Aspire5\_NB8513\_M/B Schematics Document Intel Whiskey Lake U-Processor with DDR4 REV3.0 2019-03-14

Author	Albert Zhou	 HUAQIN 华勤通信 Huaqin Telecom Technology Com.,Ltd.		
Reviewer	Albert Zhou	Page name:	Cover page	
Approver	Lobo_Fan	Size: A4	Project Name: NB8513	REV: V1.0
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# EE MB Block Diagram





MEM ID

HW_ID0	HW_ID1	HW_ID2	Description	Total
0	0	0	4x Micron 8Gbx16 MT40A512M16TB-062E:J	4GB
1	0	0	4x Micron 8Gbx16 MT40A512M16LY-075:E	4GB
0	1	0	4x Hynix 8Gbx16 H5AN8G6NCJR-VKC	4GB
1	1	0	NA	NA
0	0	1	4x 16Gb(reserve)	8GB
1	0	1	4x 16Gb(reserve)	8GB
0	1	1	4x 16Gb(reserve)	8GB

GPU ID

HW_ID3	HW_ID4	Description
0	0	UMA
1	0	N17-G0
0	1	N17-G1
1	1	N17-G2

G-sensor ID

HW_ID5	Description
0	no g-sensor
1	G-sensor on board


FP ID

HW_ID6	Description
0	no FP
1	FP on board

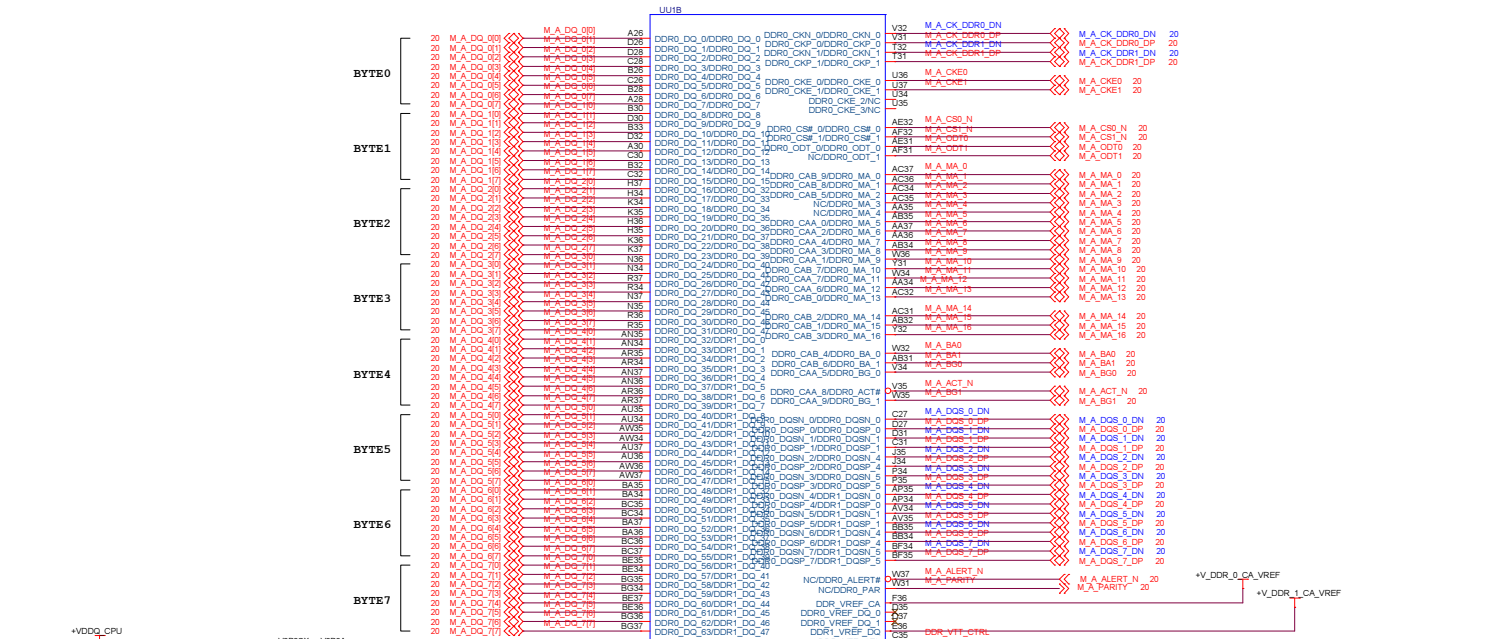
TPM and fTPM ID

HW_ID7	Description
0	fTPM
1	TPM



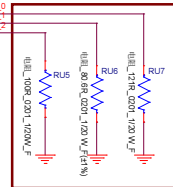
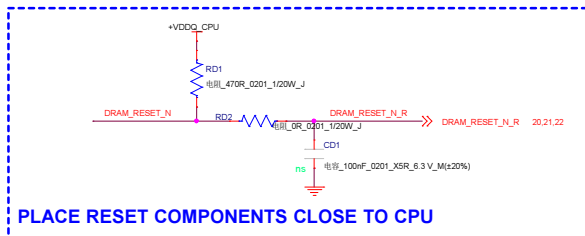
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<b>A4</b>	<b>NB8513</b>		<b>V1.0</b>
<b>Date:</b>	<b>Friday, March 22, 2019</b>	<b>Sheet:</b>	<b>72</b>







		U41C			
BYTE0	21	M.B.DQ_000	M.B.DQ_000	J22	AF28 M.B.CK_DDR0_DN
	21	M.B.DQ_001	M.B.DQ_001	H26	AF29 M.B.CK_DDR0_DP
	21	M.B.DQ_002	M.B.DQ_002	G22	AE28 M.B.CK_DDR0_DP
	21	M.B.DQ_003	M.B.DQ_003	F26	AE29
BYTE1	21	M.B.DQ_004	M.B.DQ_004	J26	T28 M.B.CKE0
	21	M.B.DQ_005	M.B.DQ_005	G26	T29
	21	M.B.DQ_006	M.B.DQ_006	H26	T29
	21	M.B.DQ_007	M.B.DQ_007	I26	T29
BYTE2	21	M.B.DQ_008	M.B.DQ_008	J26	T29
	21	M.B.DQ_009	M.B.DQ_009	K26	T29
	21	M.B.DQ_010	M.B.DQ_010	L26	T29
	21	M.B.DQ_011	M.B.DQ_011	M26	T29
BYTE3	21	M.B.DQ_012	M.B.DQ_012	N26	T29
	21	M.B.DQ_013	M.B.DQ_013	O26	T29
	21	M.B.DQ_014	M.B.DQ_014	P26	T29
	21	M.B.DQ_015	M.B.DQ_015	Q26	T29
BYTE4	21	M.B.DQ_016	M.B.DQ_016	R26	T29
	21	M.B.DQ_017	M.B.DQ_017	S26	T29
	21	M.B.DQ_018	M.B.DQ_018	T26	T29
	21	M.B.DQ_019	M.B.DQ_019	U26	T29
BYTE5	21	M.B.DQ_020	M.B.DQ_020	V26	T29
	21	M.B.DQ_021	M.B.DQ_021	W26	T29
	21	M.B.DQ_022	M.B.DQ_022	X26	T29
	21	M.B.DQ_023	M.B.DQ_023	Y26	T29
BYTE6	21	M.B.DQ_024	M.B.DQ_024	Z26	T29
	21	M.B.DQ_025	M.B.DQ_025	AA26	T29
	21	M.B.DQ_026	M.B.DQ_026	AB26	T29
	21	M.B.DQ_027	M.B.DQ_027	AC26	T29
BYTE7	21	M.B.DQ_028	M.B.DQ_028	AD26	T29
	21	M.B.DQ_029	M.B.DQ_029	AE26	T29
	21	M.B.DQ_030	M.B.DQ_030	AF26	T29
	21	M.B.DQ_031	M.B.DQ_031	AG26	T29

**BOM NOTE**

CFL-U43e/WHLU42:  
[01]:121  
[1]:80.6  
[2]:100  
CFL-U42:  
100/100/100

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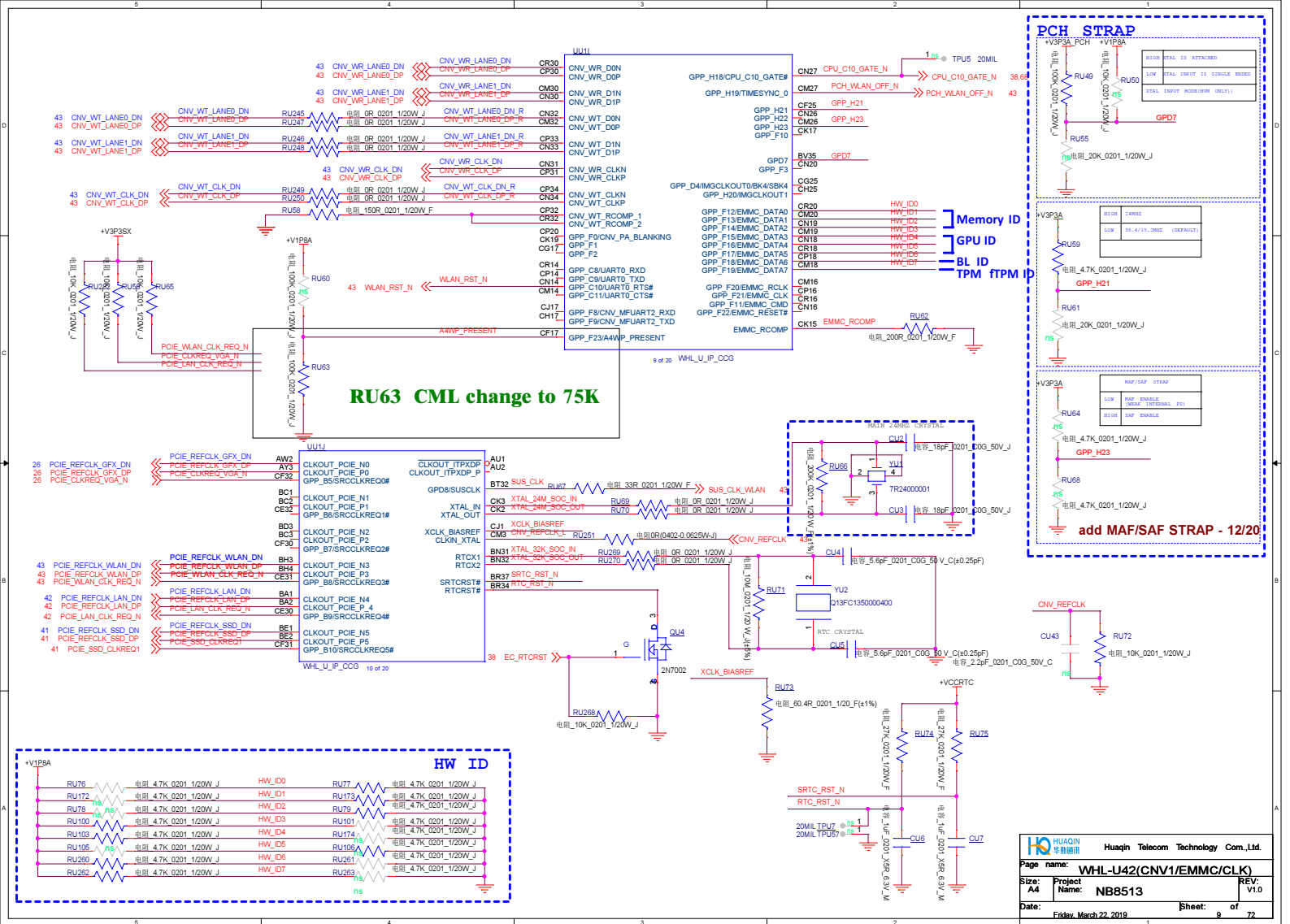








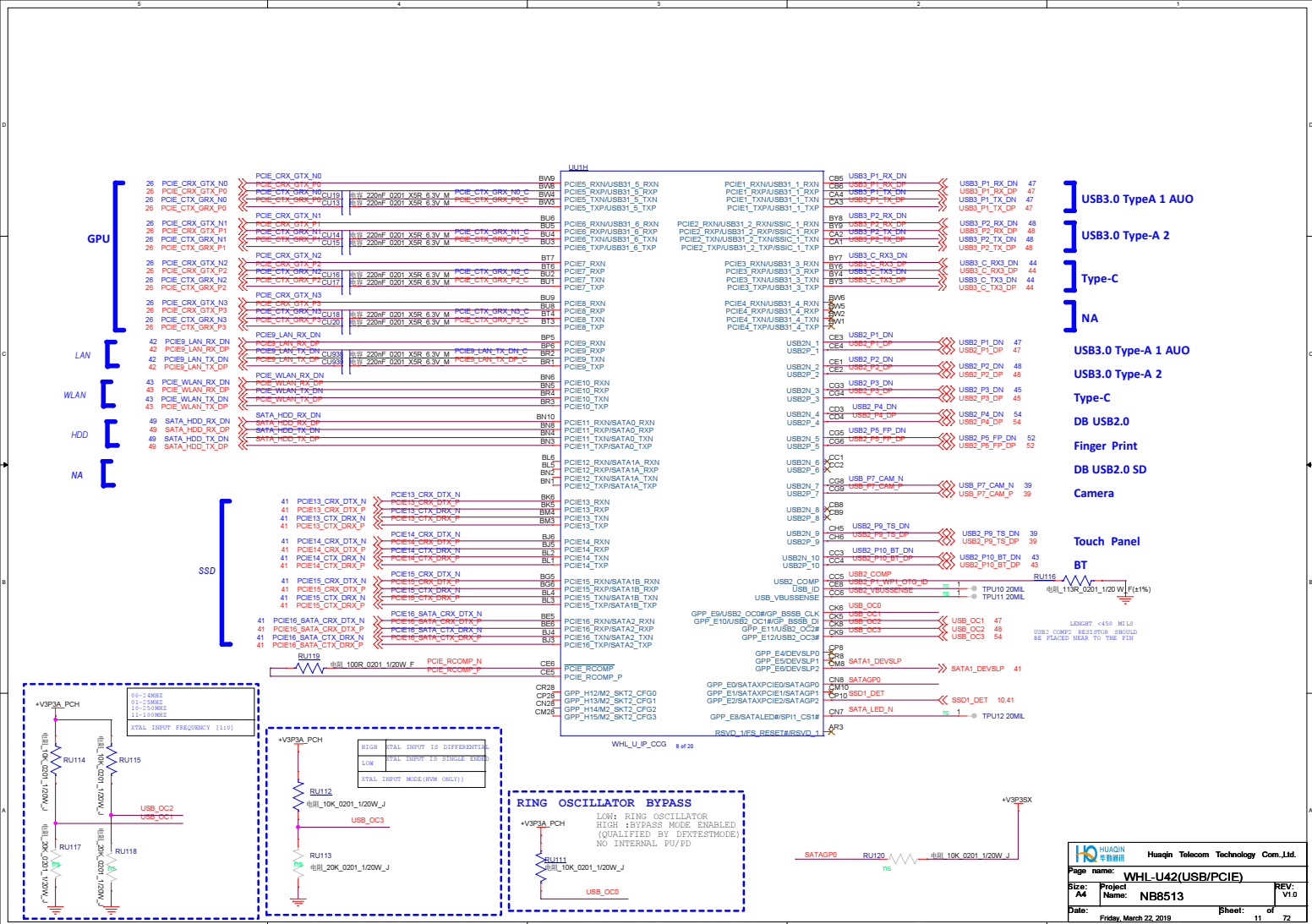




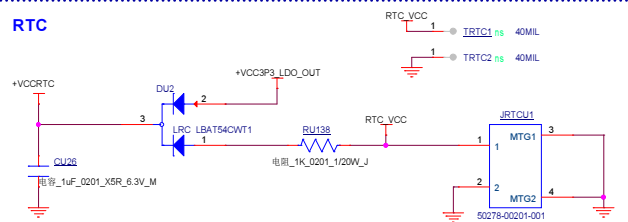
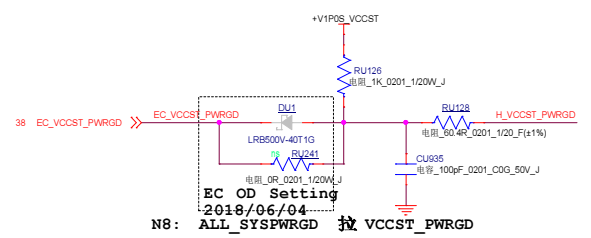
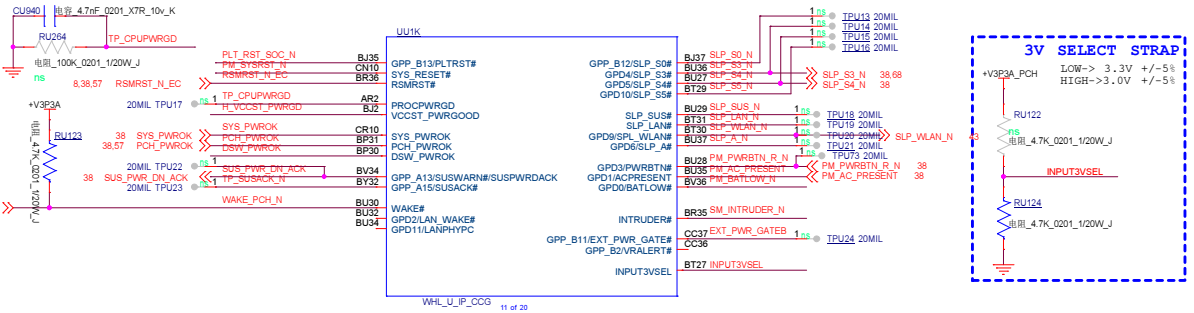









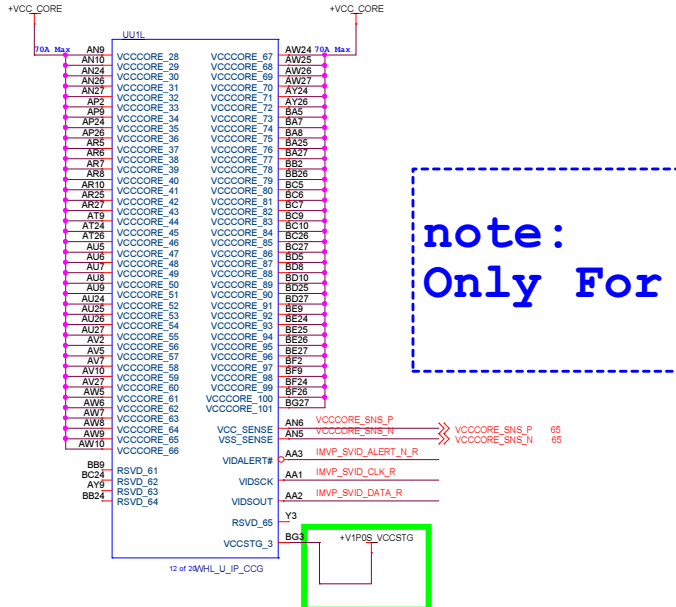




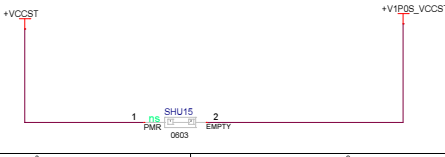
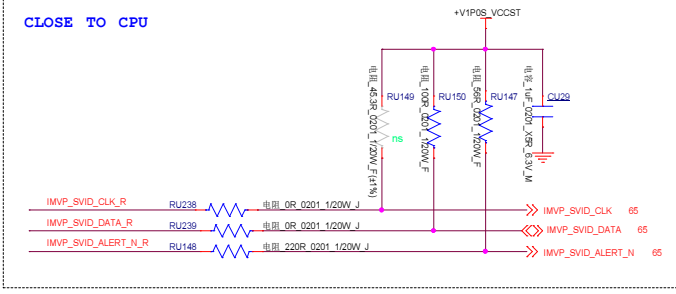
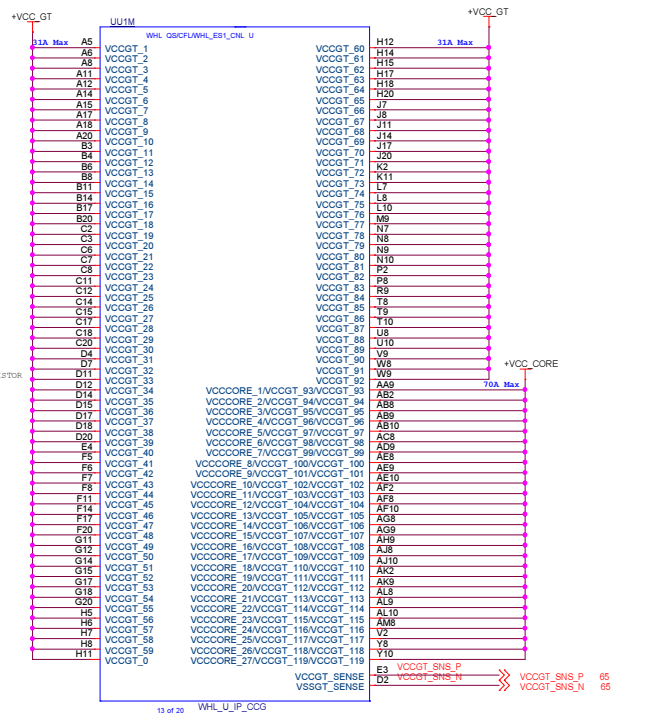
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note:  
Only For ES2

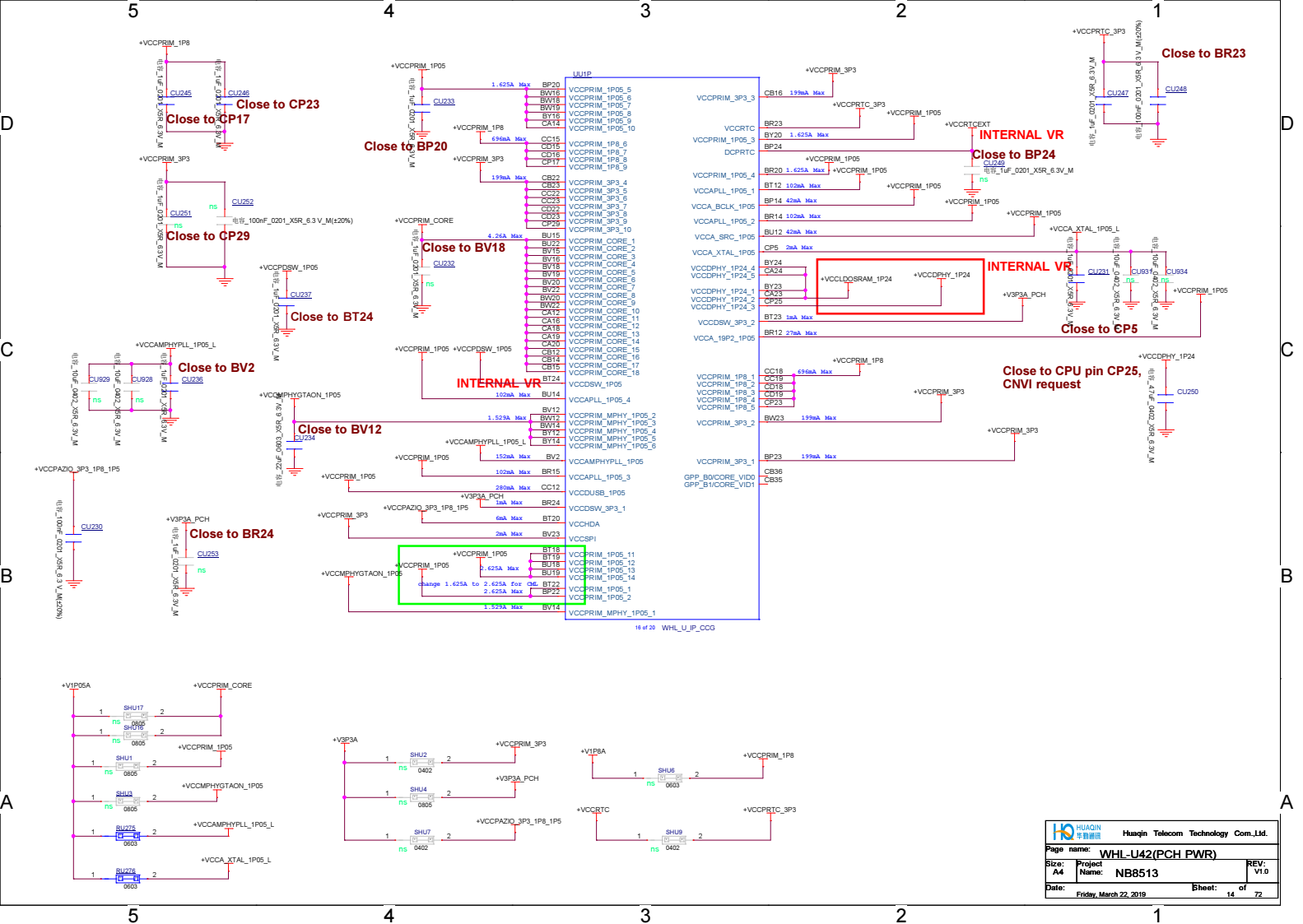


CAUTION:  
PLACE THE PU RESISTOR  
CLOSE TO CPU

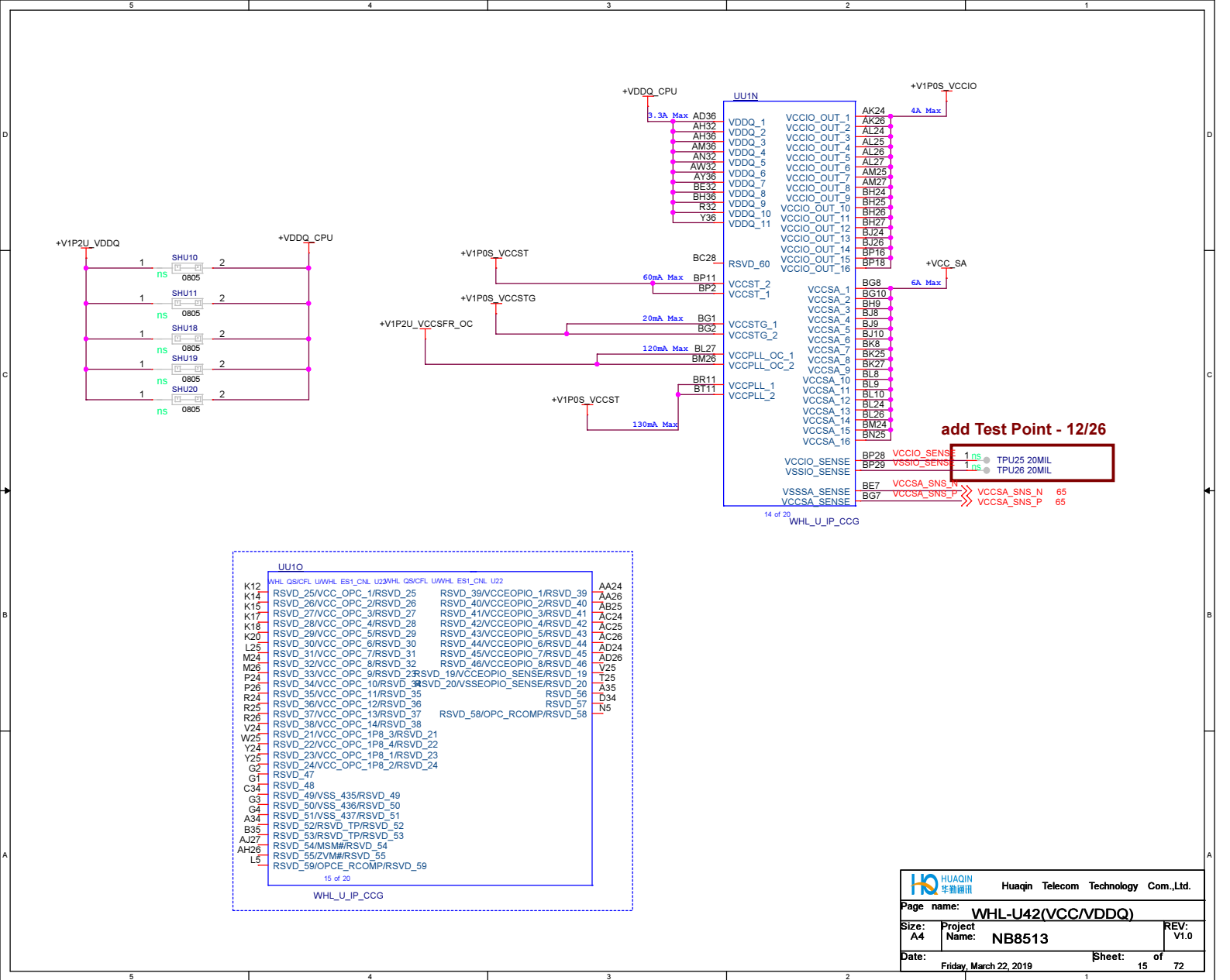


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UUIR			
CP34	VSS_342	VSS_330	AE25
BT5	VSS_361	VSS_337	BM33
CP35	VSS_361	VSS_345	CM5
CP37	VSS_371	VSS_354	AE27
CP38	VSS_381	VSS_364	BM35
AW1	VSS_391	VSS_374	CM9
CM1	VSS_401	VSS_384	AE30
ES6	VSS_411	VSS_392	BM36
AT4	VSS_421	VSS_398	CM13
ES4	VSS_360	VSS_315	AE27
ES5	VSS_370	VSS_322	BM9
AE4	VSS_380	VSS_336	AE27
AE26	VSS_400	VSS_344	BM30
AE28	VSS_410	VSS_353	CM11
AE24	VSS_420	VSS_363	AP3
AE29	VSS_428	VSS_373	BM15
AE24	VSS_434	VSS_395	CM25
AE25	VSS_395	VSS_301	AP30
ES	VSS_390	VSS_307	CM25
ES3	VSS_359	VSS_314	AP33
ES6	VSS_369	VSS_321	BM15
CM7	VSS_379	VSS_328	AP36
CM8	VSS_389	VSS_334	AP4
CM9	VSS_399	VSS_343	CM5
CM10	VSS_409	VSS_352	AE7
CM11	VSS_419	VSS_362	BM25
CM12	VSS_427	VSS_372	CM9
AE3	VSS_433	VSS_425	AG10
ES3	VSS_341	VSS_432	BM4
AE3	VSS_349	VSS_294	CM1
ES3	VSS_358	VSS_300	BM32
CM36	VSS_368	VSS_306	CM11
AE3	VSS_378	VSS_313	AE27
BM10	VSS_388	VSS_320	BM33
CM4	VSS_398	VSS_327	CM13
AE37	VSS_408	VSS_334	AE28
BM2	VSS_418	VSS_405	BM4
CM1	VSS_428	VSS_415	CM15
AE3	VSS_333	VSS_424	AE29
BM25	VSS_340	VSS_431	BM7
AE30	VSS_348	VSS_293	CM19
BM3	VSS_357	VSS_299	AE30
CM4	VSS_367	VSS_305	CM21
AE33	VSS_377	VSS_312	AE31
BM3	VSS_387	VSS_319	BM19
CM4	VSS_397	VSS_326	CM27
AE36	VSS_407	VSS_394	AE33
AE4	VSS_417	VSS_404	BM25
CM1	VSS_325	VSS_414	AE35
AE4	VSS_333	VSS_423	CM37
BM7	VSS_339	VSS_430	AE35
CM13	VSS_347	VSS_392	BT15
AE3	VSS_355	VSS_398	AE28
ES6	VSS_365	VSS_304	BT16
CM11	VSS_375	VSS_311	CM9
AE10	VSS_385	VSS_318	AE7
ES6	VSS_395	VSS_383	CM2
CM11	VSS_405	VSS_393	AE3
AE27	VSS_317	VSS_403	CM38
ES6	VSS_324	VSS_413	AE33
CM25	VSS_331	VSS_422	DM1
AE30	VSS_338	VSS_429	AE36
AE30	VSS_346	VSS_291	BT25
CM29	VSS_355	VSS_309	DM5
ES3	VSS_365	VSS_310	AE4
CM31	VSS_375	VSS_310	BT28
AE33	VSS_385	VSS_323	AE4
ES3	VSS_395	VSS_382	BT33
CM33	VSS_399	VSS_382	DM
AE36	VSS_316	VSS_402	AE28
VSS_323	VSS_412		

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WHL\_U\_IP\_CCG

UUIS			
BT35	VSS_277	VSS_180	BT5
AL32	VSS_290	VSS_183	AU32
BT36	VSS_185	VSS_186	BT28
ES8	VSS_185	VSS_245	BT1
VSS31	VSS_172	VSS_207	AV33
ES9	VSS_208	VSS_270	BT33
AM10	VSS_217	VSS_181	BT4
BT11	VSS_227	VSS_181	AV38
ES23	VSS_238	VSS_181	BT35
AM28	VSS_250	VSS_189	BT3
ES27	VSS_263	VSS_175	AV3
VSS216	VSS_276	VSS_244	AV33
AM33	VSS_289	VSS_182	BT36
ES29	VSS_155	VSS_233	AV33
AM35	VSS_164	VSS_244	AV3
BU24	VSS_200	VSS_256	AV36
ES1	VSS_207	VSS_259	CM1
BD25	VSS_216	VSS_283	CM1
ES33	VSS_229	VSS_150	AV4
AV25	VSS_237	VSS_180	CM1
BU7	VSS_249	VSS_168	CM2
ES9	VSS_262	VSS_174	AV6
AN28	VSS_275	VSS_178	CM2
BM11	VSS_154	VSS_232	K4
F12	VSS_154	VSS_232	AV5
AN29	VSS_194	VSS_243	CM9
F15	VSS_199	VSS_255	K3
AN30	VSS_206	VSS_268	AW28
F18	VSS_215	VSS_282	CM3
AN31	VSS_225	VSS_149	CM7
BM3	VSS_238	VSS_159	AW29
F2	VSS_248	VSS_187	CM4
AN7	VSS_261	VSS_173	K28
BM31	VSS_274	VSS_212	AW3
F21	VSS_287	VSS_221	CM
AN8	VSS_189	VSS_231	K9
BM33	VSS_193	VSS_242	AW30
F24	VSS_198	VSS_254	CM11
BM4	VSS_205	VSS_287	K3
F3	VSS_214	VSS_281	AW31
AP3	VSS_214	VSS_188	CM15
BM11	VSS_235	VSS_158	CM1
F4	VSS_247	VSS_166	AY33
AP3	VSS_250	VSS_203	K3
BM15	VSS_273	VSS_211	K31
CM1	VSS_185	VSS_220	AY35
AP38	VSS_188	VSS_230	K3
CM7	VSS_192	VSS_241	BT2
AP4	VSS_197	VSS_253	K4
G33	VSS_204	VSS_266	BT6
AP28	VSS_213	VSS_280	CM25
G35	VSS_223	VSS_147	K9
G36	VSS_234	VSS_197	BT8
AT33	VSS_246	VSS_196	CM11
BM24	VSS_259	VSS_202	L27
G9	VSS_272	VSS_210	BT1
AT35	VSS_286	VSS_219	L33
HT1	VSS_153	VSS_229	BT3
AT36	VSS_163	VSS_240	L35
BM7	VSS_171	VSS_252	B25
HT2	VSS_177	VSS_285	CM18
AT4	VSS_181	VSS_279	L36
BY11	VSS_184	VSS_146	BM7
AU10	VSS_187	VSS_190	CM19
BY15	VSS_191	VSS_195	L6
G9	VSS_258	VSS_201	BM3
AU28	VSS_271	VSS_209	CM2
BY22	VSS_285	VSS_218	N22
AT2	VSS_162	VSS_228	BT3
AU29	VSS_170	VSS_251	CM30
AT5	VSS_176	VSS_254	N27
VSS_178	VSS_278		CM25

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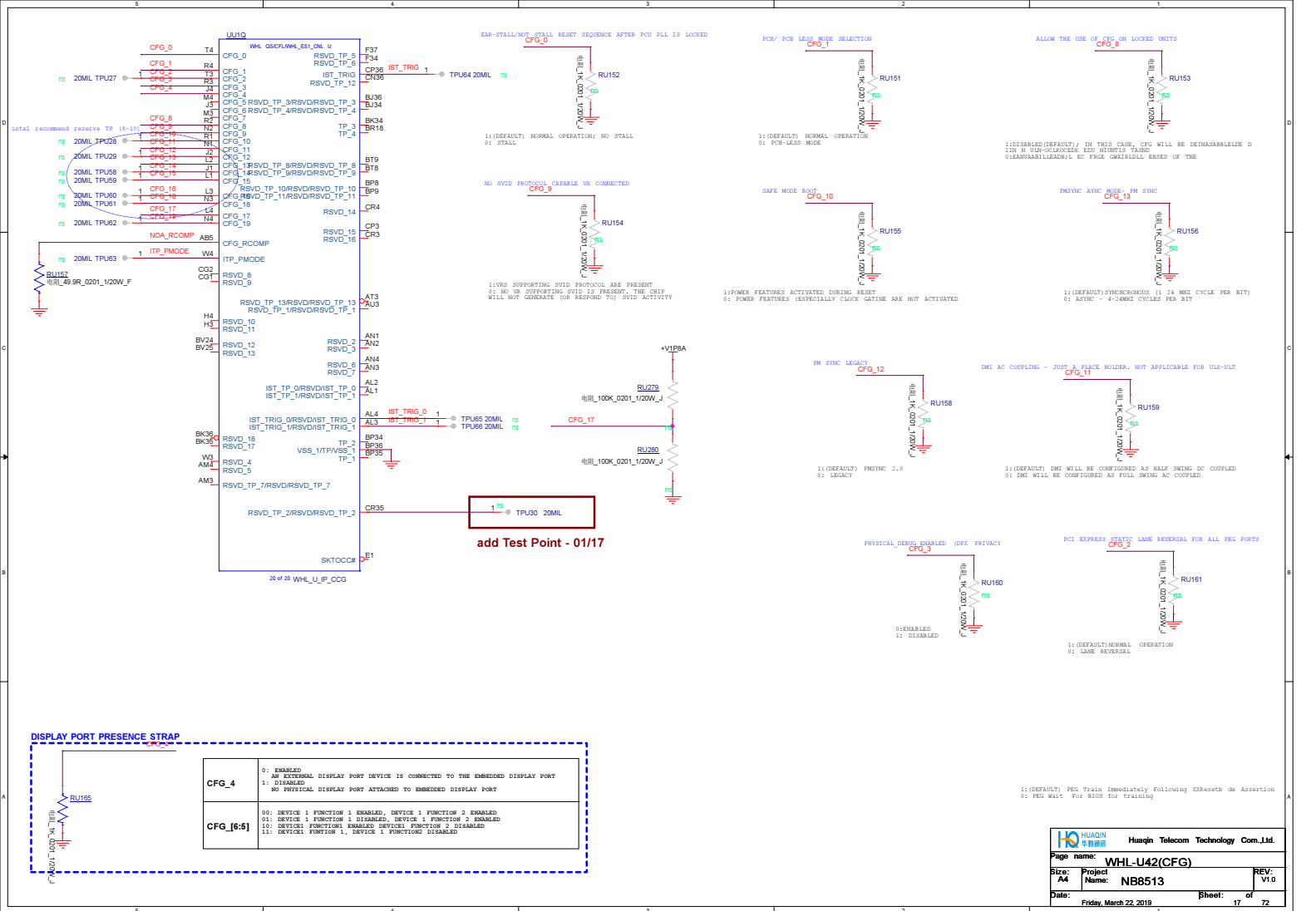
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N6	VSS_56	VSS_59	CF23
BM3	VSS_73	VSS_108	BM2
P10	VSS_79	VSS_115	CF28
BM5	VSS_89	VSS_139	W10
CM33	VSS_95	VSS_8	CF3
BT	VSS_102	VSS_19	BM31
CM4	VSS_110	VSS_29	CF4
P33	VSS_122	VSS_83	W30
BM9	VSS_132	VSS_87	BM3
CM7	VSS_145	VSS_92	CM33
P36	VSS_14	VSS_98	W7
BM10	VSS_25	VSS_105	BM33
CM11	VSS_35	VSS_114	CF2
P4	VSS_44	VSS_125	BM36
BA28	VSS_42	VSS_138	Y28
BM7	VSS_59	VSS_7	BM4
BA3	VSS_65	VSS_18	CM31
CM30	VSS_72	VSS_77	Y27
BM7	VSS_78	VSS_82	BM25
BM3	VSS_131	VSS_86	BM30
CM35	VSS_144	VSS_91	CM29
BM8	VSS_13	VSS_97	CM11
BM33	VSS_24	VSS_104	BM25
CM28	VSS_34	VSS_113	CM14
BM9	VSS_43	VSS_124	Y35
CM36	VSS_51	VSS_137	BM23
BM38	VSS_58	VSS_6	CF19
BM3	VSS_64	VSS_70	CF19
BM4	VSS_71	VSS_76	BM29
CM7	VSS_119	VSS_81	CM23
BM3	VSS_130	VSS_85	BM32
CM25	VSS_143	VSS_90	CM28
CM11	VSS_12	VSS_96	BM33
L27	VSS_23	VSS_103	CM33
CM12	VSS_33	VSS_112	CF23
L30	VSS_42	VSS_123	CM35
BM9	VSS_50	VSS_136	BM30
CM14	VSS_57	VSS_5	BM16
L33	VSS_63	VSS_17	BM18
BM5	VSS_109	VSS_28	CF19
BM32	VSS_118	VSS_38	CM16
CM24	VSS_129	VSS_54	CM14
L36	VSS_142	VSS_55	CM14
CM25	VSS_11	VSS_62	BM22
CM11	VSS_22	VSS_69	BM30
BM3	VSS_32	VSS_75	CM20
CM33	VSS_41	VSS_80	BM12
DM5	VSS_49	VSS_135	BM12
CM36	VSS_56	VSS_4	CM24
CM35	VSS_101	VSS_16	CM24
CM35	VSS_108	VSS_27	CM24
BM33	VSS_117	VSS_37	CM24
CM36	VSS_128	VSS_46	BM7
V26	VSS_141	VSS_54	BM4
CM35	VSS_10	VSS_61	CM24
BM7	VSS_21	VSS_68	CM24
Y27	VSS_31	VSS_74	BM4
CM36	VSS_40	VSS_122	BM4
CM11	VSS_46	VSS_134	BM4
V3	VSS_94	VSS_3	BM8
BM10	VSS_100	VSS_15	BM4
CF14	VSS_107	VSS_26	BM4
V30	VSS_116	VSS_36	BM4
BM39	VSS_127	VSS_45	CM2
CF19	VSS_140	VSS_53	CM3
V33	VSS_5	VSS_60	CM2
BM9	VSS_20	VSS_67	CM2
CF2	VSS_30	VSS_111	CM5
V36	VSS_39	VSS_121	CM5
BM3	VSS_88	VSS_133	CM8
VSS_93	VSS_2		

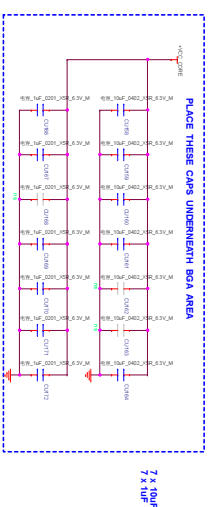
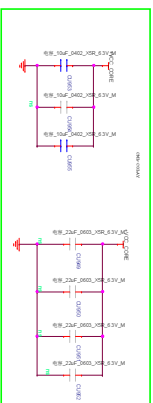
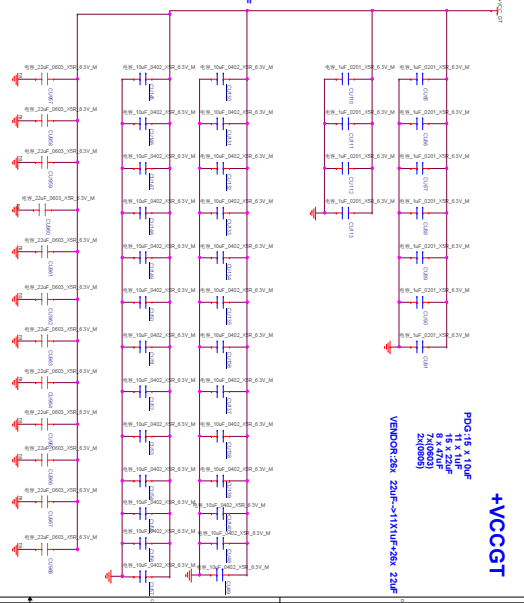
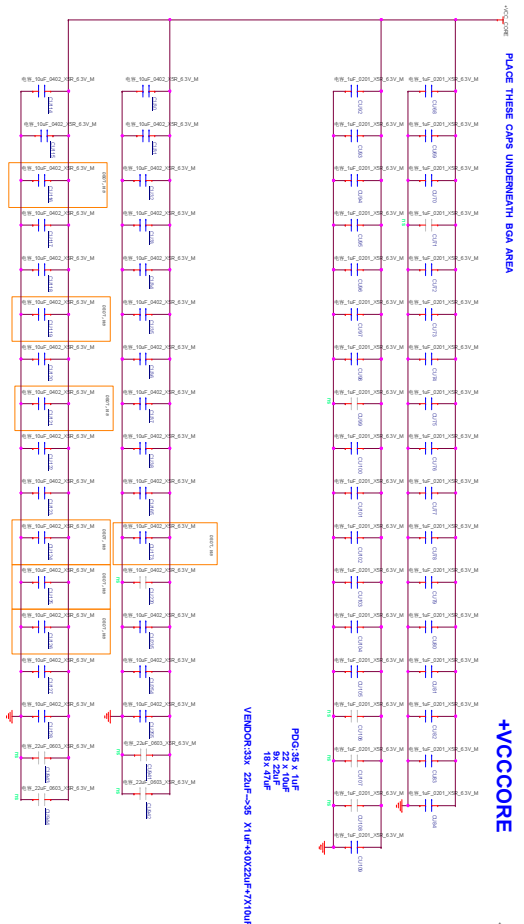
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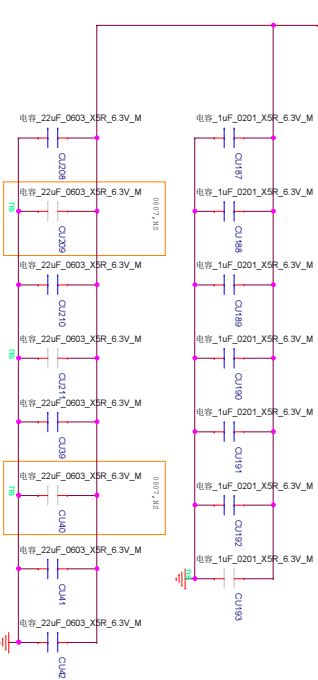


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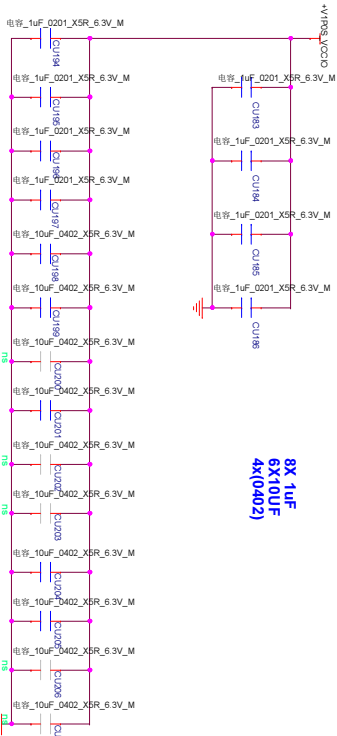


PDG:7x 1uF  
15X 10uF  
2 x 47 uF  
2 x (0805)

VENDOR:8x 22uF-->7X1uF+8X22UF



8X 1uF  
6X10UF  
4X(0402)

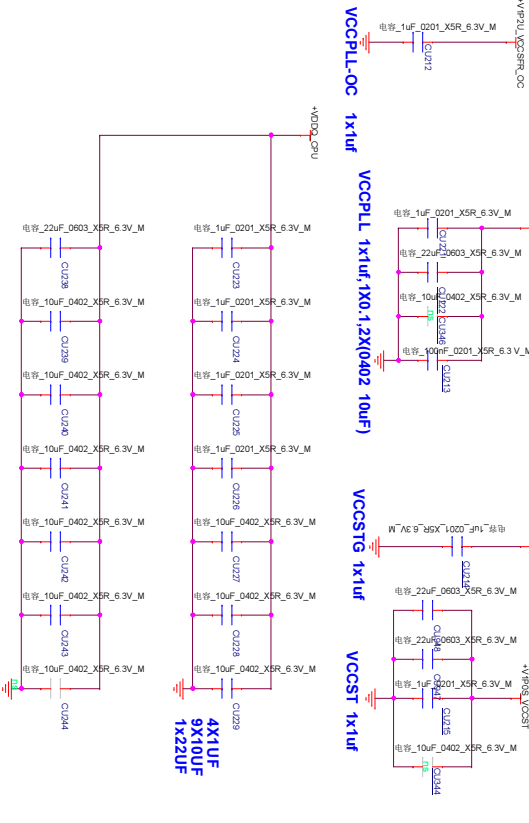


VCCPLL-OC 1x1uF

VCCPLL 1X1uF,1X0.1,2X(0402 10uF)

VCCSTG 1x1uF

VCCST 1x1uF



4X1uF  
9X10UF  
1X22UF

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Date:	Feb 24, 2019		





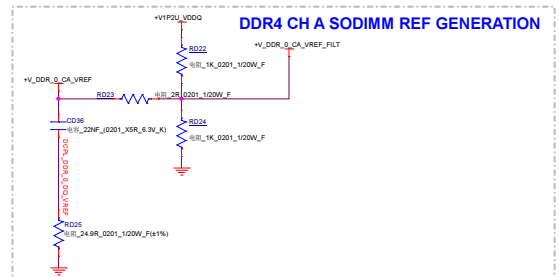
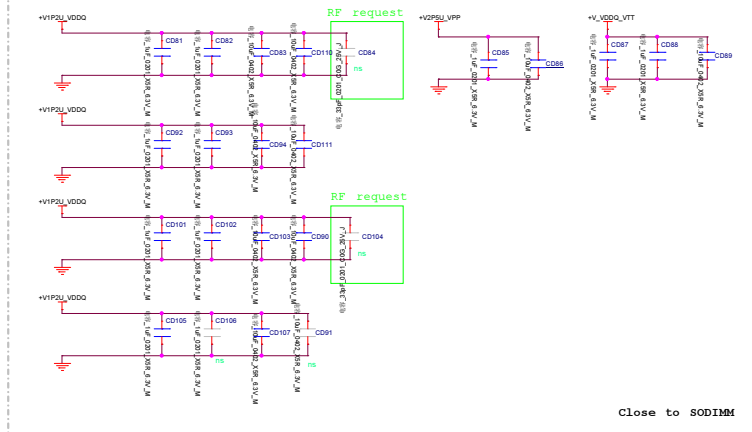
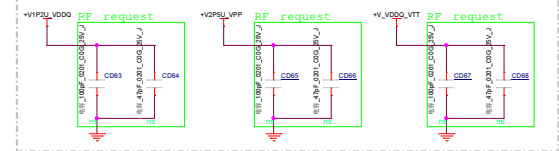
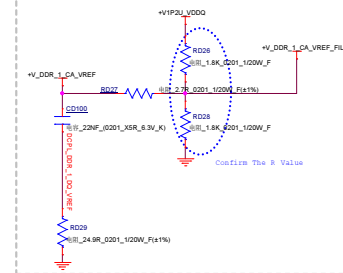
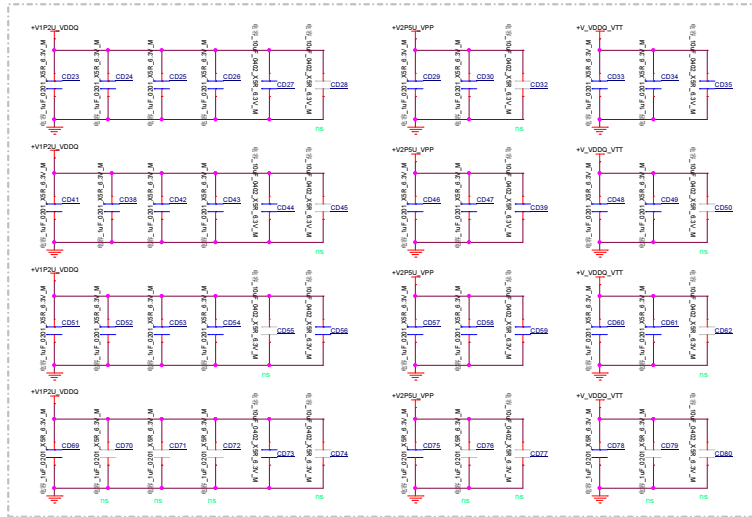










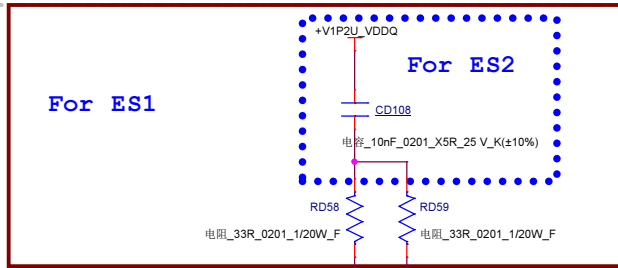
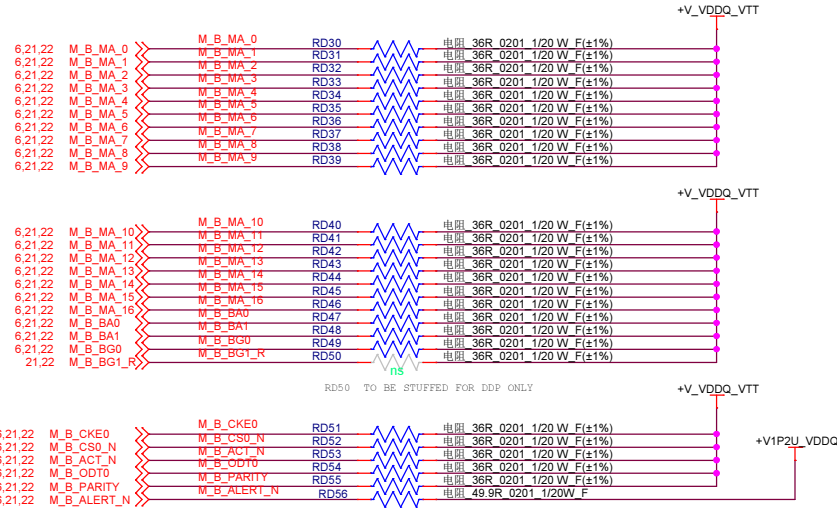


### DDR4 CH A SODIMM REF GENERATION



## MEMORY TERMINATIONS

## CHANNEL B MD




PLACE CLOSE TO CPU

PLACE TERMINATION RESISTOR CLOSE TO LAST CHIP

- 1.change +V\_VDDQ\_VTT to +V1P2U\_VDDQ
2. add CAP CD155 for ES2 sample - 01/04
3. add RD89 for ES1 sample -01/23

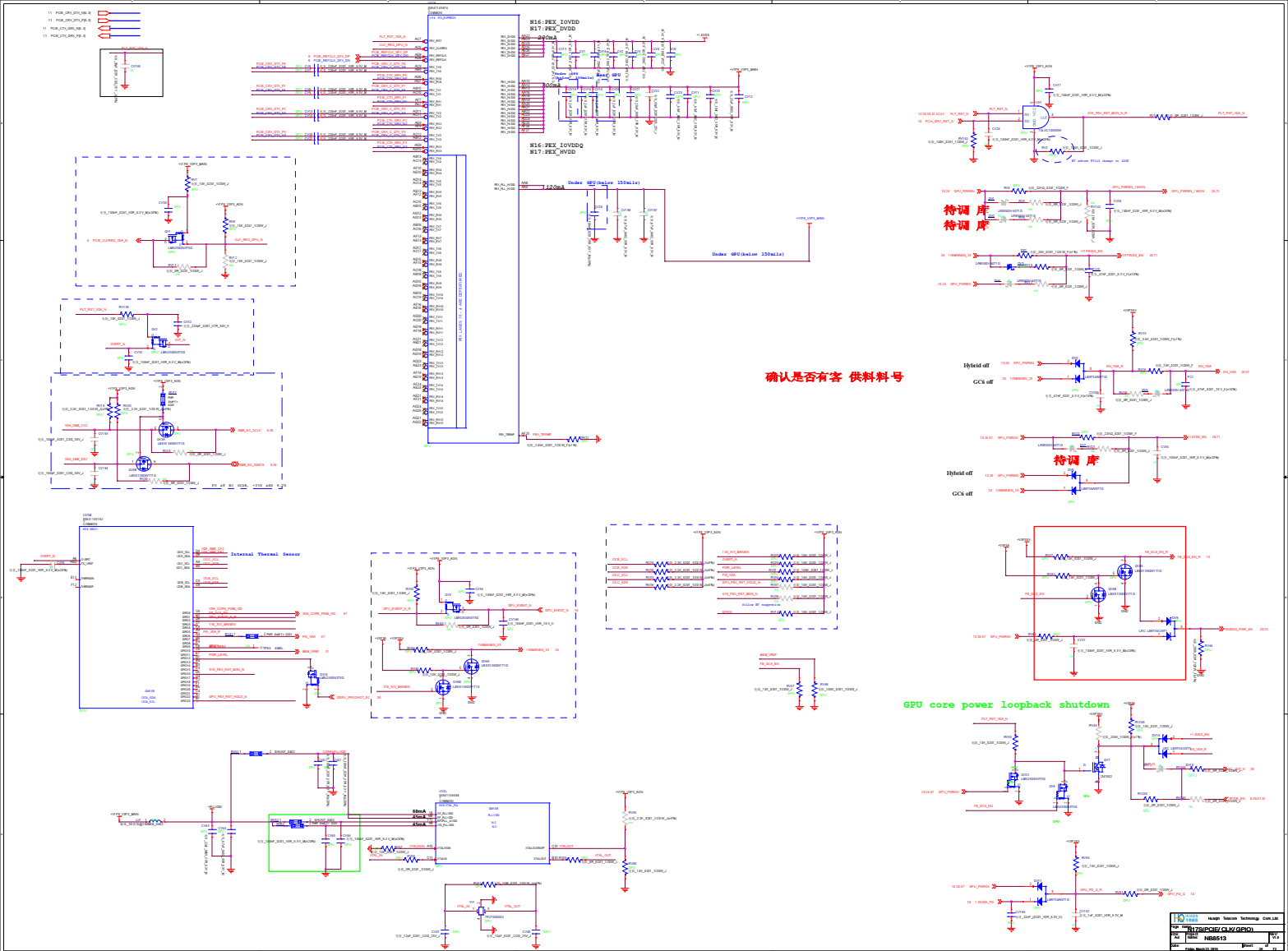
change CD146 to 3.3pF - 01/04

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Size: A4	Project Name: <b>NB8513</b>	REV: V1.0	
Date: <b>Friday, March 22, 2019</b>	Sheet: <b>24</b> of <b>72</b>		

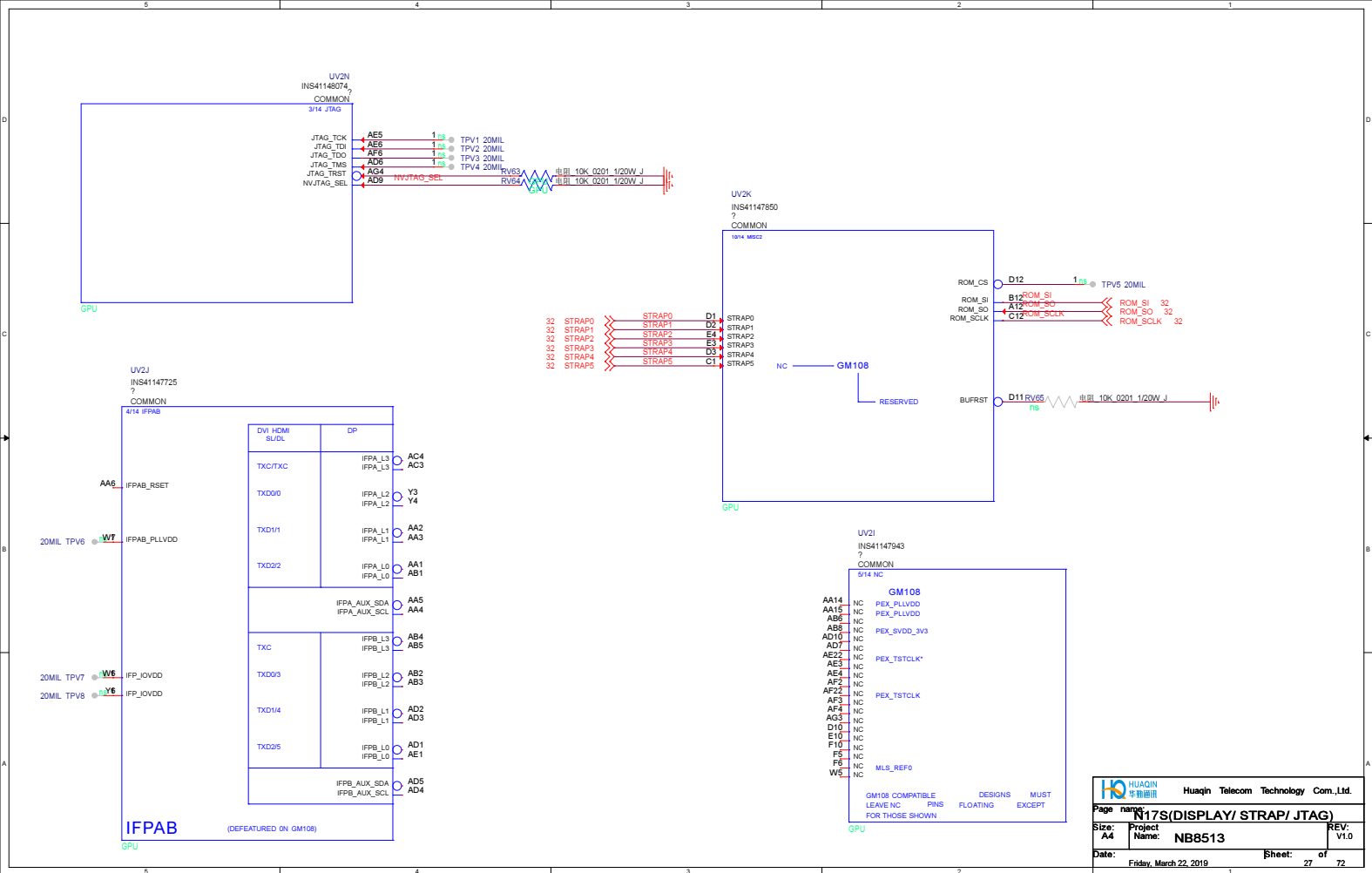














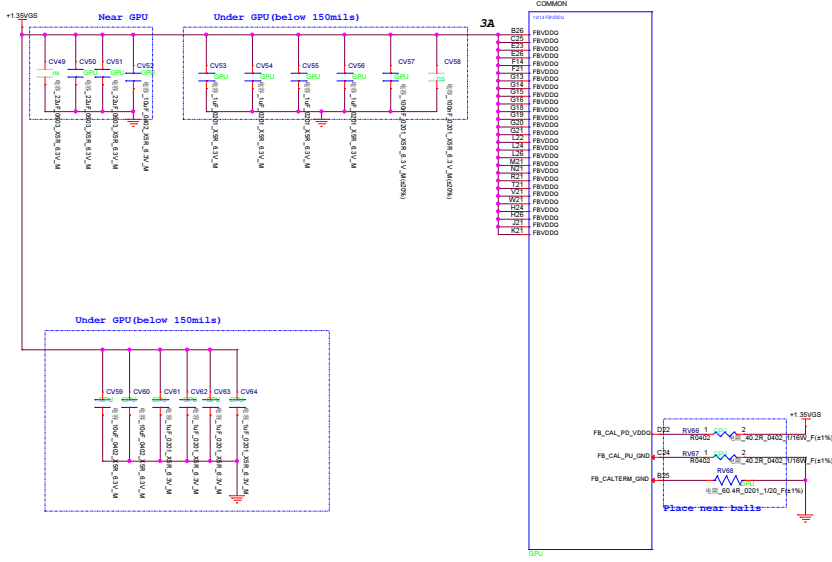
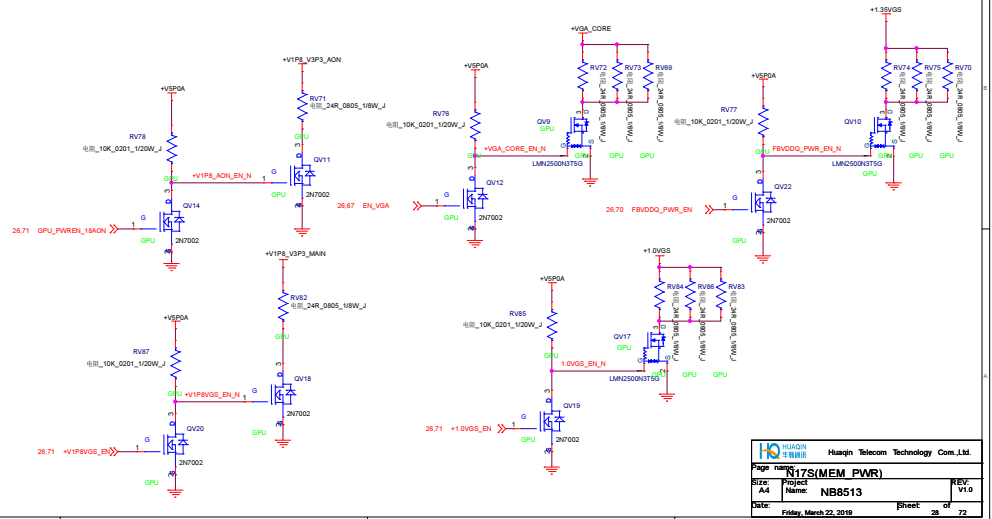


Table 9.18 GPU-Side FBVDDQ Decoupling Requirements

Decoupling Capacitor		Recommended Quantity and Placement (for all supported partitions combined)	
Capacitance	Type Size	Quantity	Placement
For N17x GPU Package: GB2C-64 (preliminary)			
1.0 uF	X6S [0402]	8	Under GPU FBVDDQ ball (evenly distributed throughout partition)
10 uF	X6S [0603]	2	
10 uF	X6S [0603]	1	Near GPU device
22 uF	X6S [0603]	3	
For N17x GPU Package: GB4C-128 (preliminary)			
1.0 uF	X6S [0402]	12	Under GPU FBVDDQ ball (equally distributed across partitions)
10 uF	X6S [0603]	4	
10 uF	X6S [0603]	2	Near GPU device
22 uF	X6S [0603]	5	
For N17x GPU Package: GB4-256			
1.0 uF	X6S [0402]	24	Under GPU FBVDDQ ball (equally distributed across partitions)
10 uF	X6S [0603]	5	
22 uF	X6S [0603]	9	Near GPU device

+VIP8A TO +VIP8\_AON

Move to Power Page 2018/06/07





7-Lead ZIF Socket  
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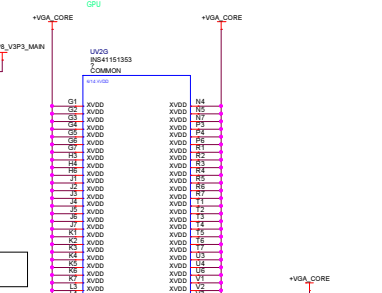
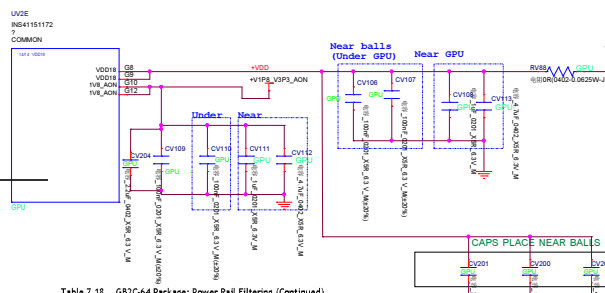
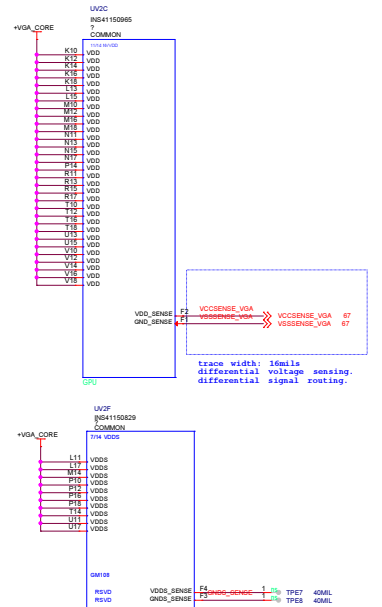
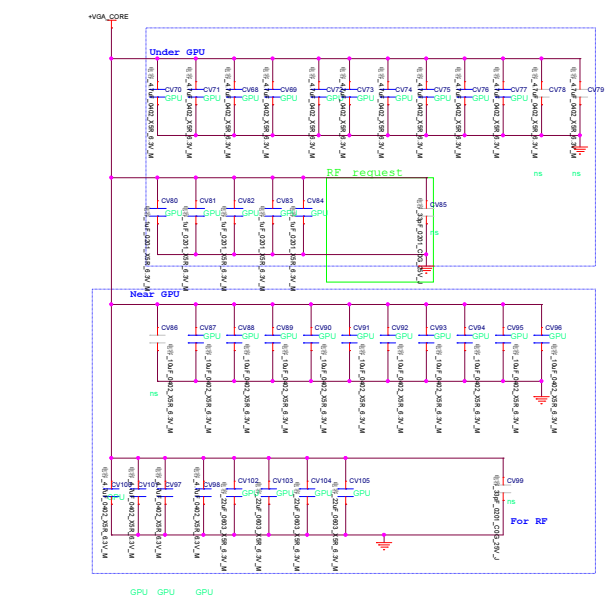
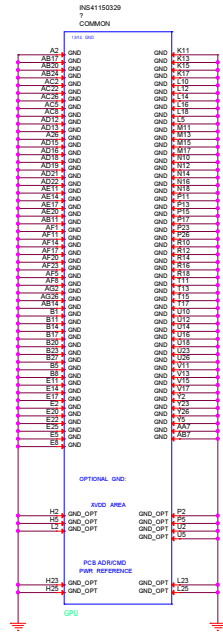
Table 7.18 GB2C-64 Package: Power Rail Filtering

Rail (GPU Ball) Name	Balls	Voltage, Current	Filtering under GPU	Filtering Near GPU
NVVDD	31	Varies	3 X 1uF (0402) 8 X 4.7uF (0603)	4 X 4.7uF (0805) 1 X 10uF (0805) 3 X 22uF (0805) 1 X 330uF (Pocscap) Near VR:
NVVDD5	10	Varies	2 X 1uF (0402) 4 X 4.7uF (0603)	2 X 10uF (0805) 7 X 10uF (0805) 1 X 22uF (0805) 1 X 330uF (Pocscap)
FBVDDQ (GPU side) <sup>1</sup>	2	1.35V 1.5V 1.55V	1 X 1uF (0402) 2 X 10uF (0603)	10uF (0603) 3 X 22uF (0603)
FBA_PLL_AVDD	1	1.6V	2 X 0.1uF (0402 X5R)	1 X 300 bead (0403 max ESR 10 mΩ)
FBR_PLL_AVDD	1	1.6V	0.1uF (0402 X5R)	1 X 22uF (0805)
FB_REPLL_AVDD	1	1.6V	1 X 0.1uF (0402 X5R)	1 X 22uF (0805)
IFPAB_PLL_VDD	2	1.6V	2 X 0.1uF (0402 X5R)	1 X 300 bead (0403 max ESR 0.01 Ω)
GPCPLL_AVDD	2	1.6V	1 X 0.1uF (0402 X5R)	1 X 22uF (0805)
SP_PLL_VDD	1	1.6V	1 X 0.1uF (0402 X5R)	1 X 4.7uF (0402)
VIO_PLL_VDD	1	1.0V	2 X 0.1uF (0402 X5S)	1 X 4.7uF (0603) 1 X 1uF (0402)


Table 7.18 GB2C-64 Package: Power Rail Filtering (Continued)

Rail (GPU Ball) Name	Balls	Voltage, Current	Filtering under GPU	Filtering Near GPU
PEX_HVDD	14	1.8V	4 X 1uF (0402 X5R)	Near GPU: 2 X 4.7uF (0603) 1 X 10uF (0805) 1 X 22uF (0805)
PEX_PLL_HVDD	2	1.8V	1 X 0.1uF (0402)	Near GPU: 2 X 4.7uF (0603) 2 X 10uF (0805) 1 X 22uF (0805)
PEX_DIVDD	6	1.0V	2 X 1uF (0402 X5R)	Near GPU: 1 X 4.7uF (0603) 2 X 10uF (0805) 1 X 22uF (0805)
1VR_MAIN	2	1.8V	2 X 0.1uF (0402)	1 X 1uF (0402) 1 X 4.7uF (0603)
1VR_AON	2	1.8V	2 X 0.1uF (0402)	1 X 4.7uF (0603)

Note:  
1. Also see Section 9.2.2.1-10.1

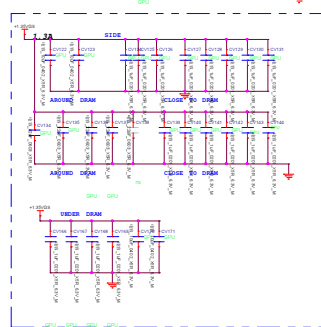
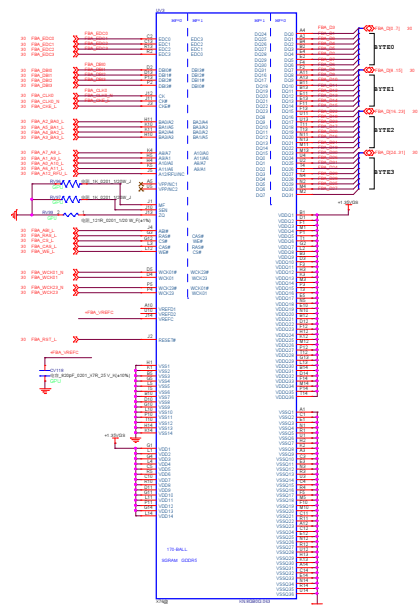




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Size: <b>A4</b>	Project Name: <b>NB8513</b>
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## Memory - Lower 32 bits



## Memory - Upper 32 bits

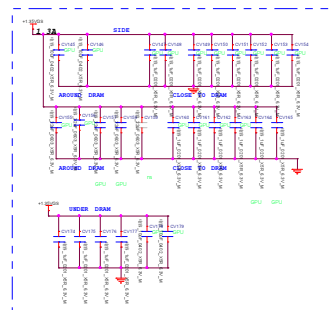
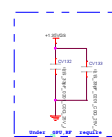
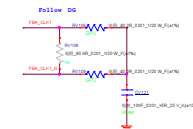
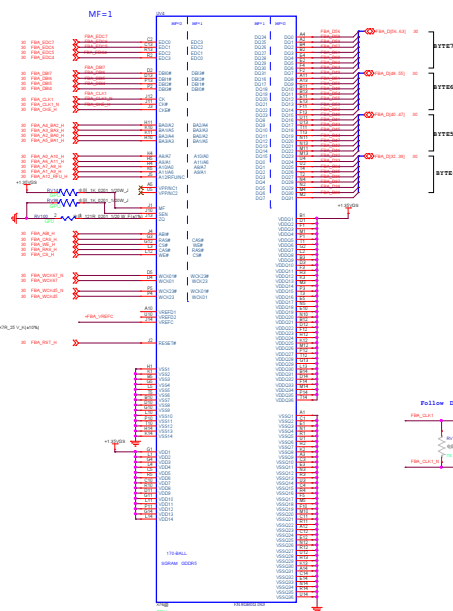
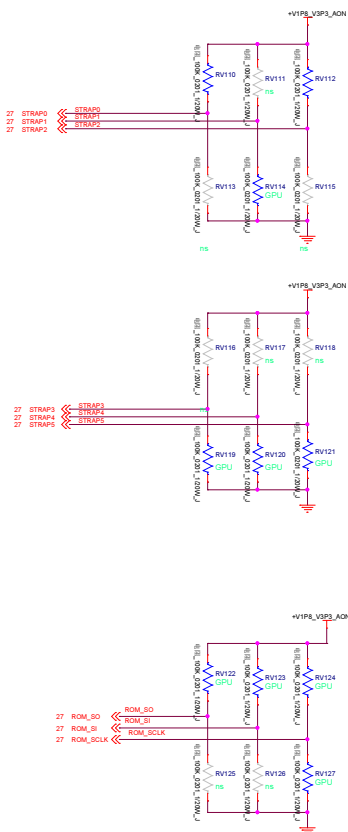


Table 9.19 DRAM-Side FBVDD/FBVDDQ Decoupling (Combined Rail)

Decoupling Capacitors		Recommended Quantity and Placement	
Capacitance	Type [Size]	Quantity	Placement (by DRAM Interface Mode)
Combined FBVDD-FBVDDQ rail			
1.0 uF	X5S [0402]	10	For x32 DRAM: Under the DRAM FBVDD or FBVDDQ ball.
10 uF	X5S [0603]	4	For x16 DRAM: In a "clamshell" PCB configuration: As close to DRAM periphery as possible.
1.0 uF	X5S [0402]	8	For x32 DRAM: Choose x32 interface to achieve max. POR DRAM speeds. Add these additional decoupling caps under the DRAM FBVDD/Q ball; should share existing FBVDD/Q ball via if possible. See Figure 9.23 for an example.
10 uF	X5S [0603]	2	Near DRAM device. Ensure at least 2 GND vias and 2 power vias for each capacitor.
22 uF	X5S [0603]	5	For 4 GHz WCK (8 Gbps data rates): Near DRAM device. Ensure at least 2 GND vias and 2 power vias for each capacitor.



For N17



GPU	Vendor	Manufacturer	Strap	Strap2	Strap1	Strap0
N17S-G1	Samueng	K4GB0325FB-HC25	0x0	L	L	L
	Micron	MT51J256M32HF-701A	0x1	L	L	H
	Hynix	H5GC8H24AJR-R0C	0x2	L	H	L
	Micron	MT51J256M32HF-701B	0x4	H	L	L
	Hynix	H5GC8H24AJR-R0C	0x5	H	L	H
N17S-G0/G2	Micron	MT51J256M32HF-701B	0x9	L	M	L
	Hynix	H5GC8H24AJR-R2C	0xA	L	M	H

N17S-G0/G2 follow N17S-G1 with NV confirm

PN	MPN	STRAP	Vendor
H011121854000	MT51J256M32HF-701B	0x4	Micron
H011121852000	H5GC8H24AJR-R0C	0x5	Hynix
H011121870000	K4GB0325FB-HC25	0x0	Samueng

Physical Strapping pin	Power Rail	RAM_CFG[0]	RAM_CFG[0x02]	RAM_CFG[0x01]	RAM_CFG[0x00]
STRAP0		L			L
STRAP1			H		L
STRAP2		L			L

#### SMBUS\_ALT\_ADDR

0	0x0E (Default)
1	0x0C (Multi-GPU usage)

#### DEVID\_SEL

0	(Default)
1	

#### PCIE\_CFG

0	(Default)
1	

#### VGA\_DEVICE

0	3D Device (Class Code 3020)
1	VGA Device (Default)

Physical Strapping pin	Power Rail	SOR3_EXPOSED	SOR2_EXPOSED	SOR1_EXPOSED	SOR0_EXPOSED
ROM_CLK	M				
ROM_SI	H	Disable	Disable	Disable	Disable
ROM_SO	H				

Table 5.3 RAMCFG

Strap Pins See Note			RAMCFG Setting Number	
STRAP2	STRAP1	STRAP0	(see Memory RVL for memory configs corresponding to these numbers)	
L	L	L	0	(0x0000)
L	L	H	1	(0x0001)
L	H	L	2	(0x0002)
L	H	H	3	(0x0003)
H	L	L	4	(0x0004)
H	L	H	5	(0x0005)
H	H	L	6	(0x0006)
H	H	H	7	(0x0007)
L	L	M	8	(0x0008)
L	M	L	9	(0x0009)
L	M	H	10	(0x000A)
L	H	M	11	(0x000B)
M	L	L	12	(0x000C)
M	L	H	13	(0x000D)

Table 5. N17S-G0/G2 GDDR5 Recommended Memories


Memory Density	Allowed Memory Configuration	FBVDD/Q	Vendor	Manufacturer Part Number	Die Revision	Strap	Memory Speed Grade	Date Code Alert	Qual Plan	Status
8 Gb	256Mx32 512Mx16	1.35V	Micron	MT51J256M32HF-80-B	B-die	0x9	8 Gbps	N/A	Full	Production ready
			Hynix	H5GC8H24AJR-R2C	A-die	0xA	8 Gbps	N/A	Full	Production ready

Notes:

- For N17S-G0/G2, the maximum allowable memory case temperature is 85 °C.
- N17S-G0/G2 running at 3.0 GHz (without intent to run 3.5 GHz at a later stage) shall also use the memory configurations in Table 4 for N17S-G1.




5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

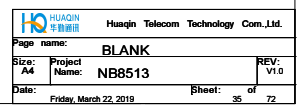
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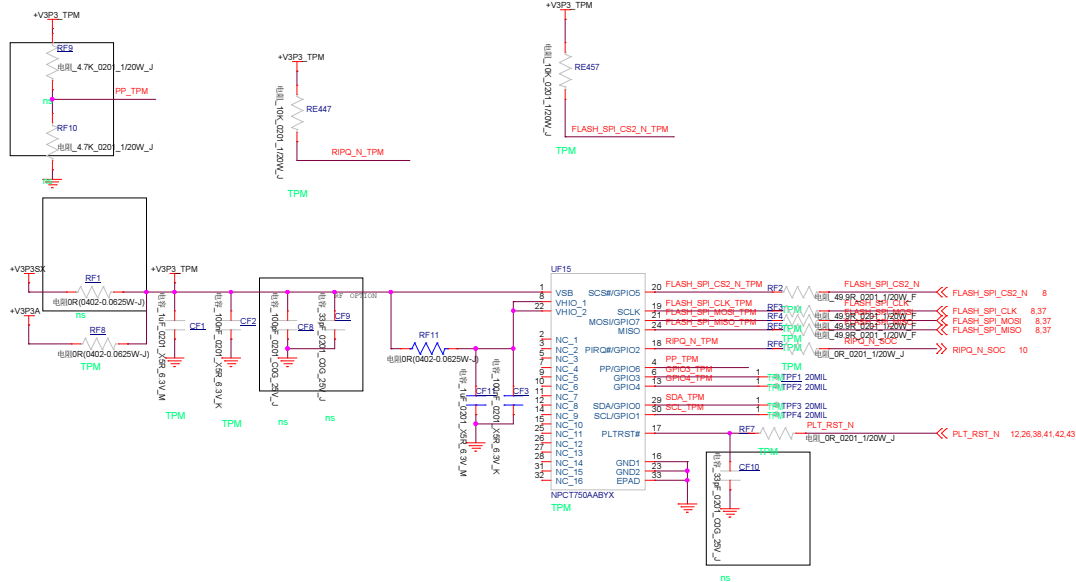
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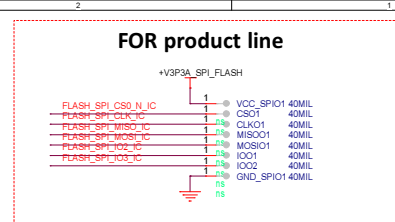
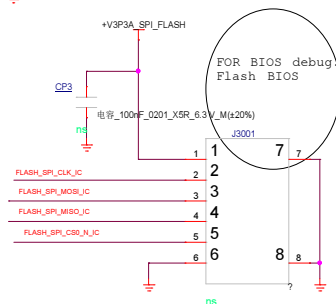




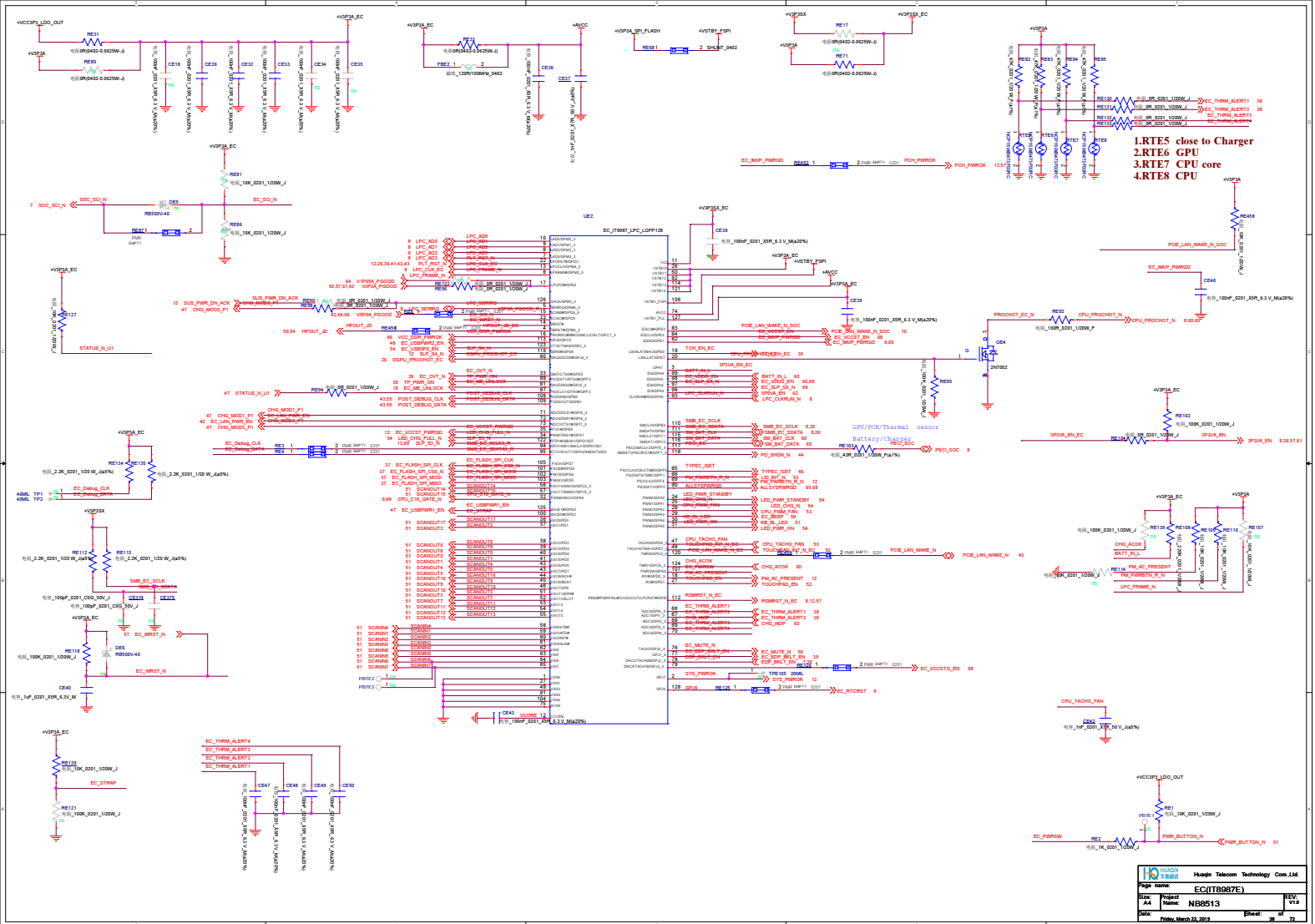




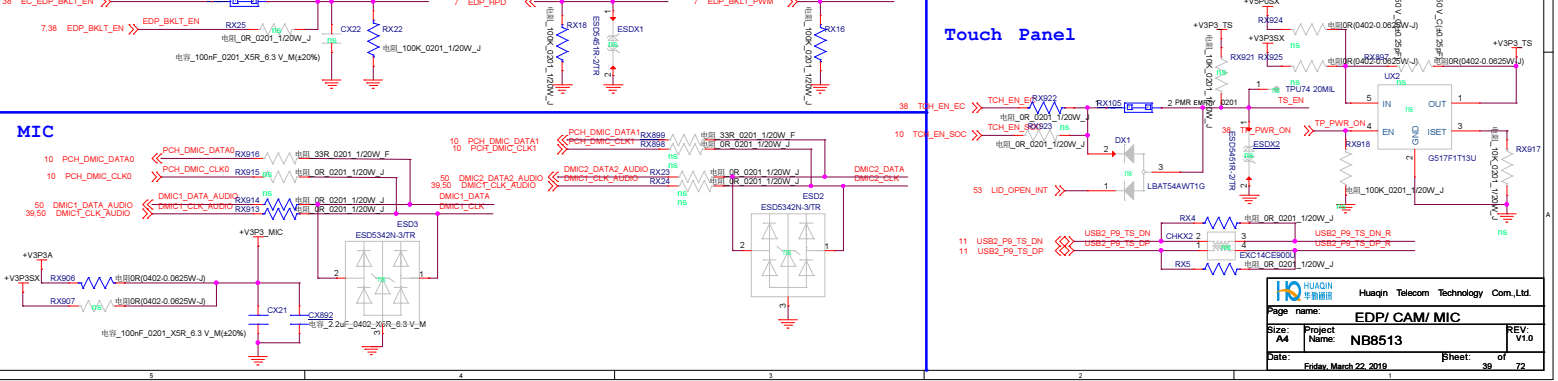
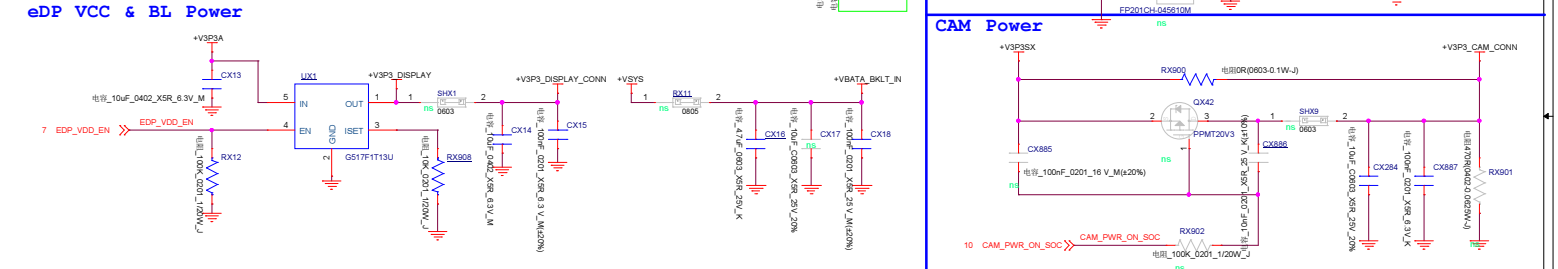
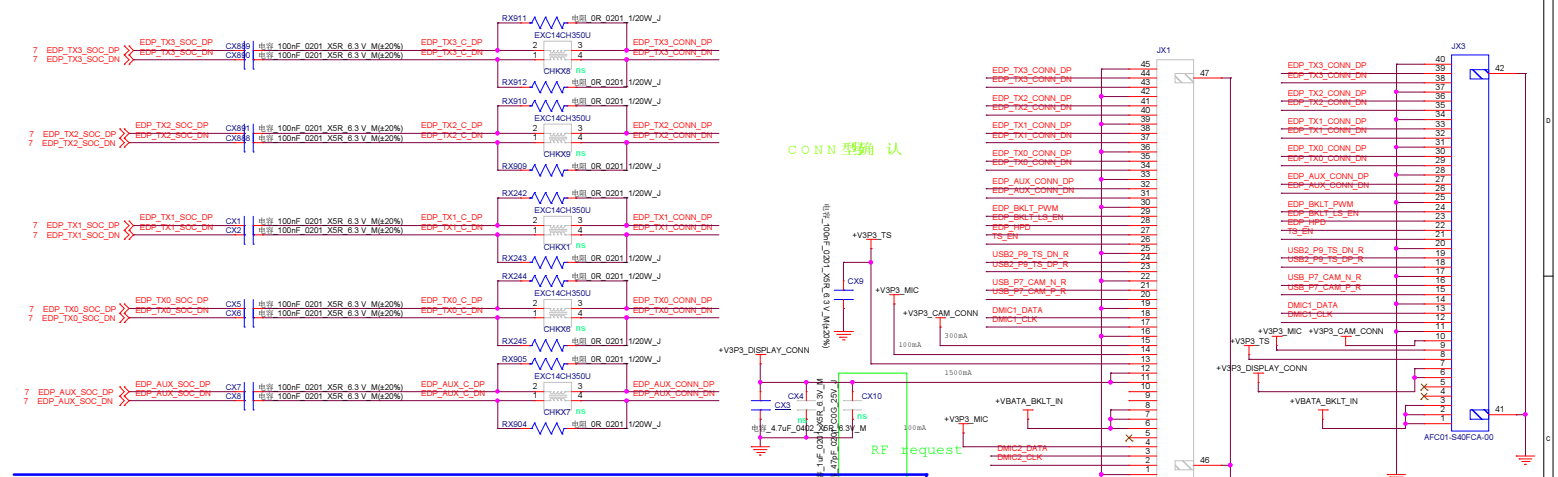


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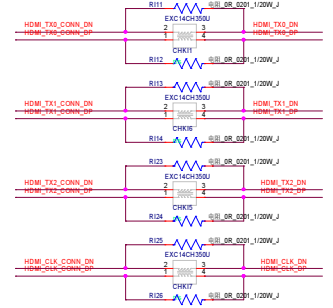
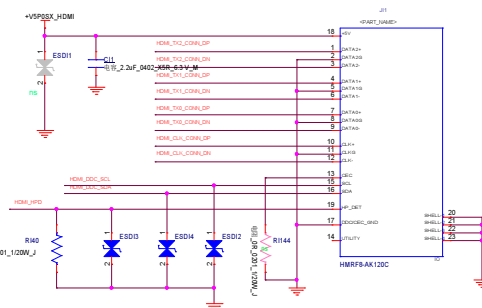
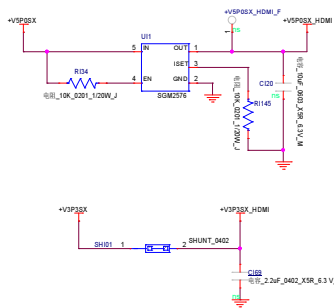




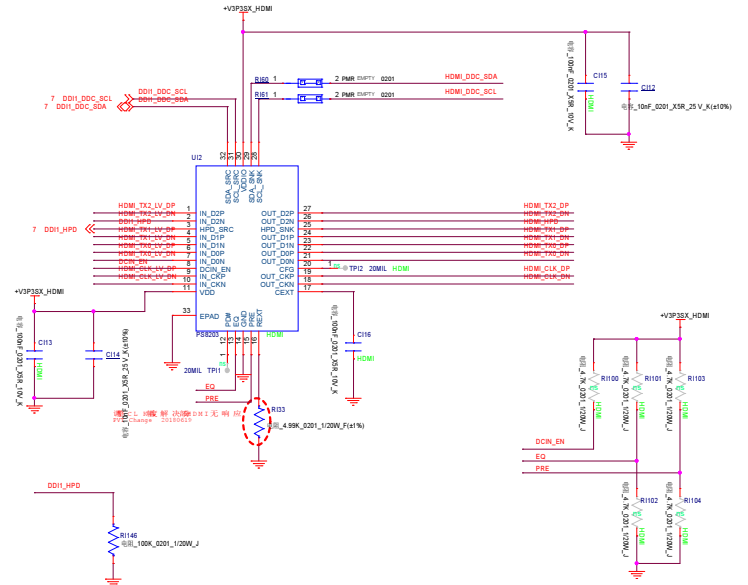
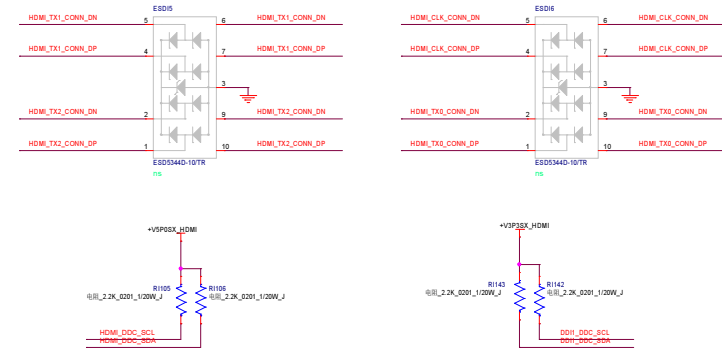
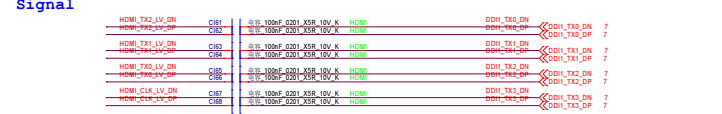





## Signal



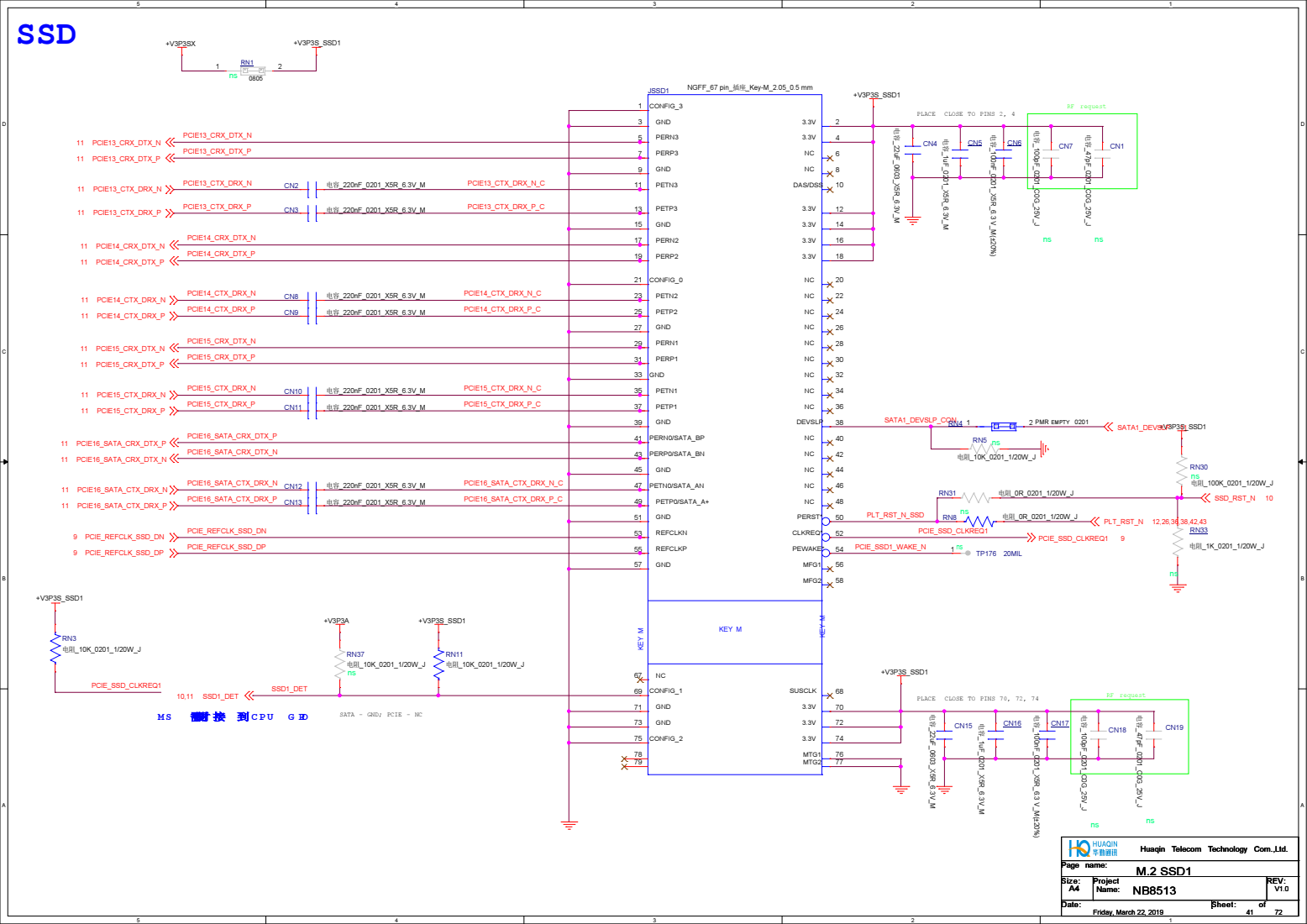
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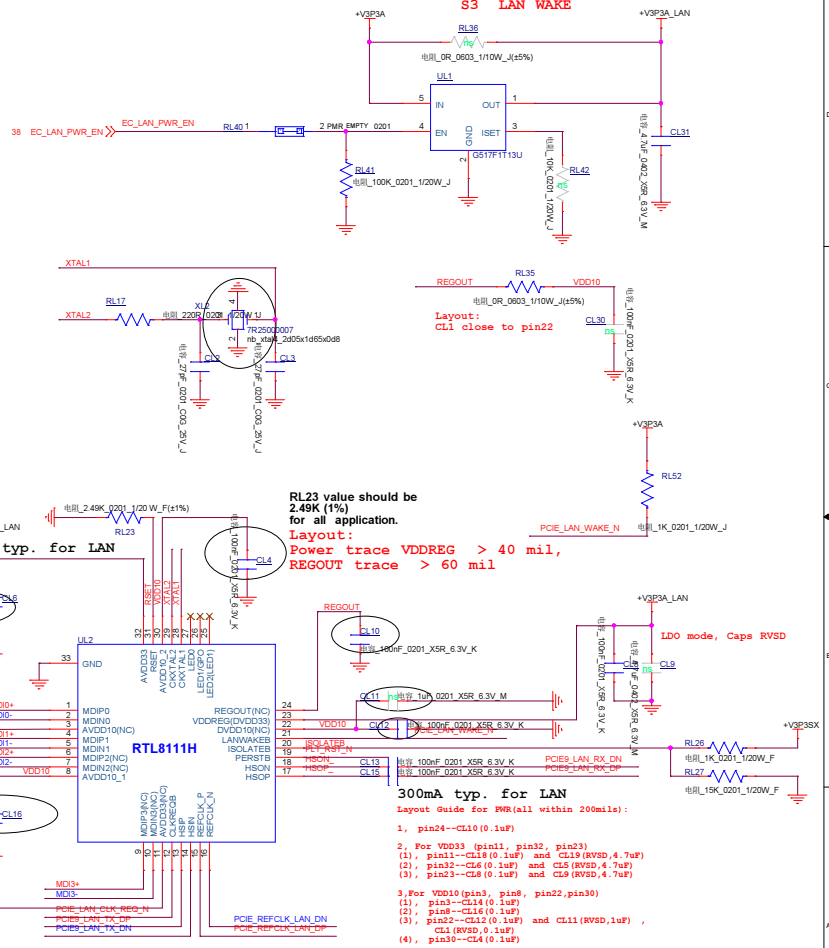
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## SSD



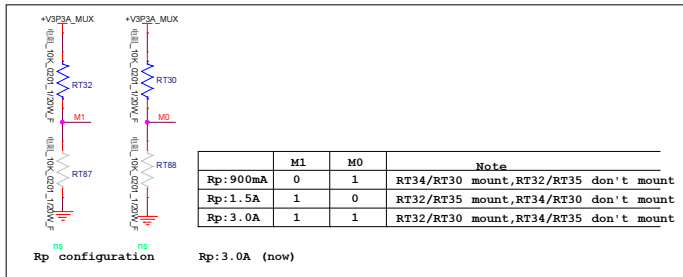








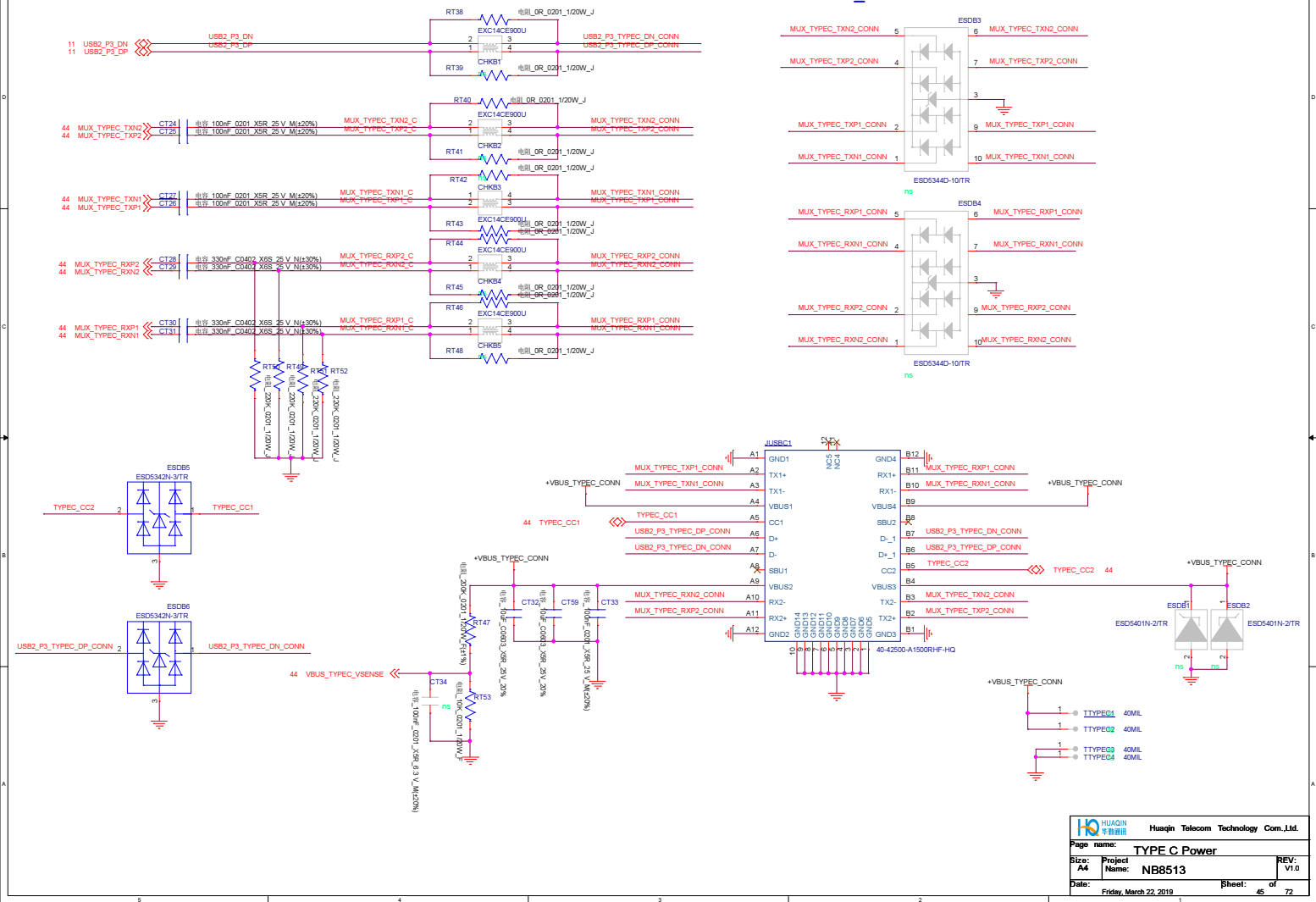




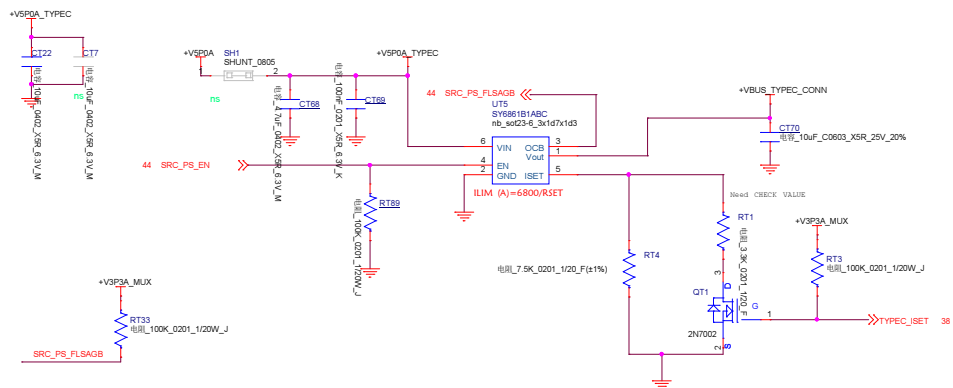
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# TYPE-C ESD

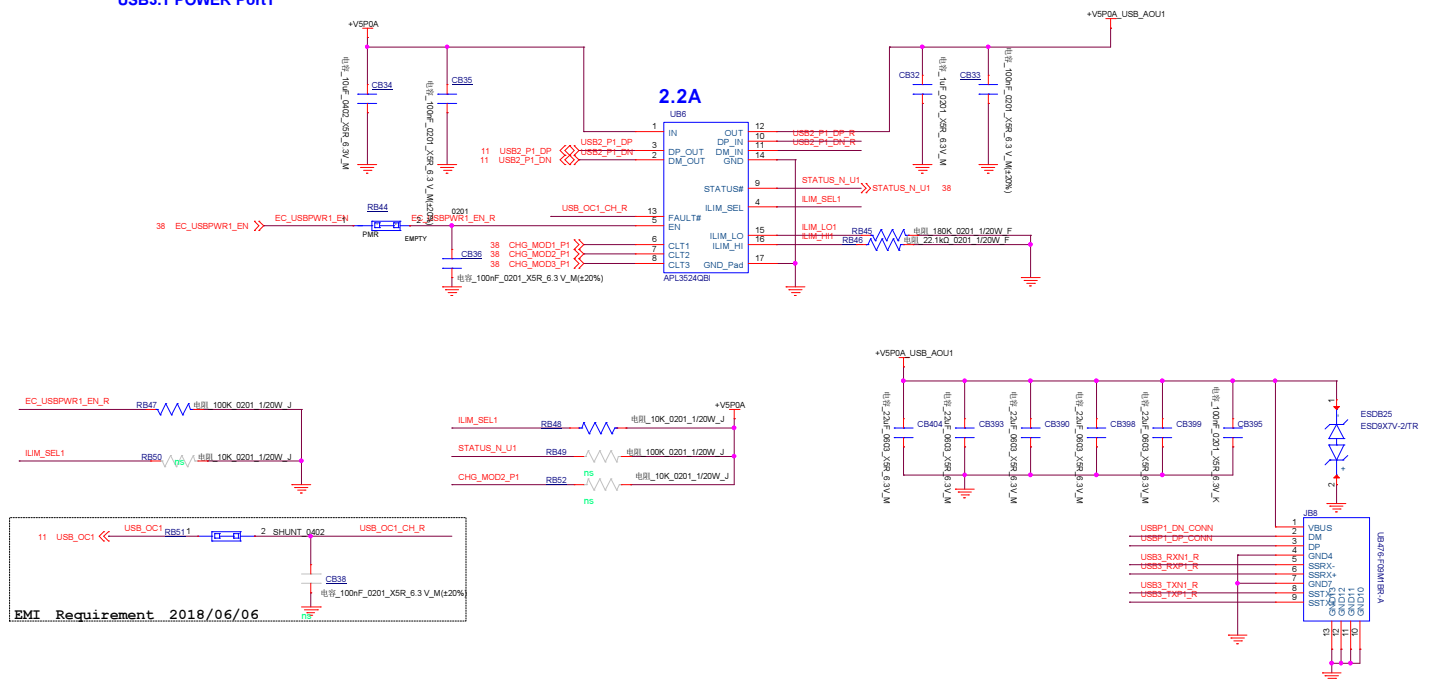




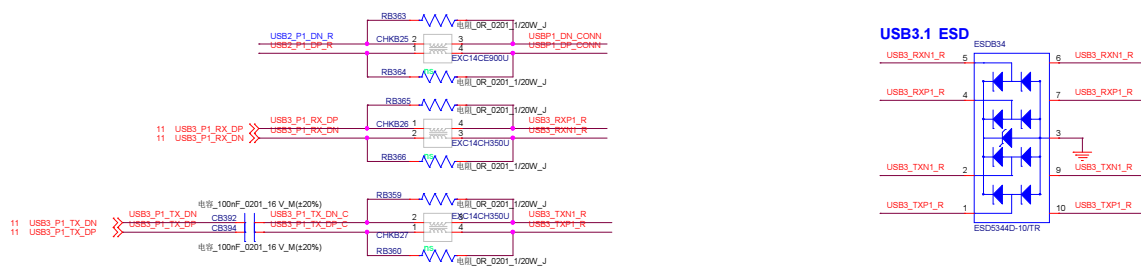





**USB3.1 POWER Port1**

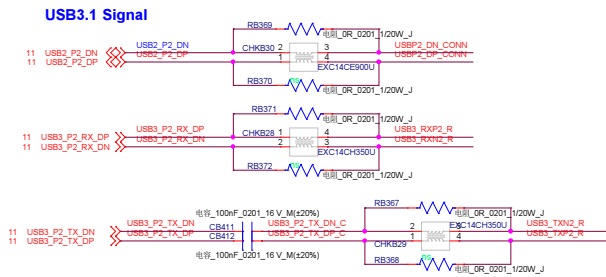
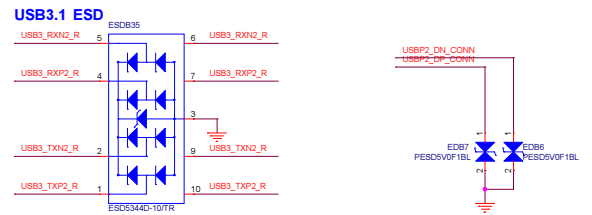
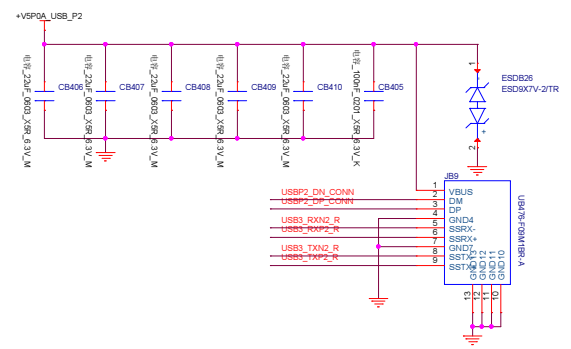



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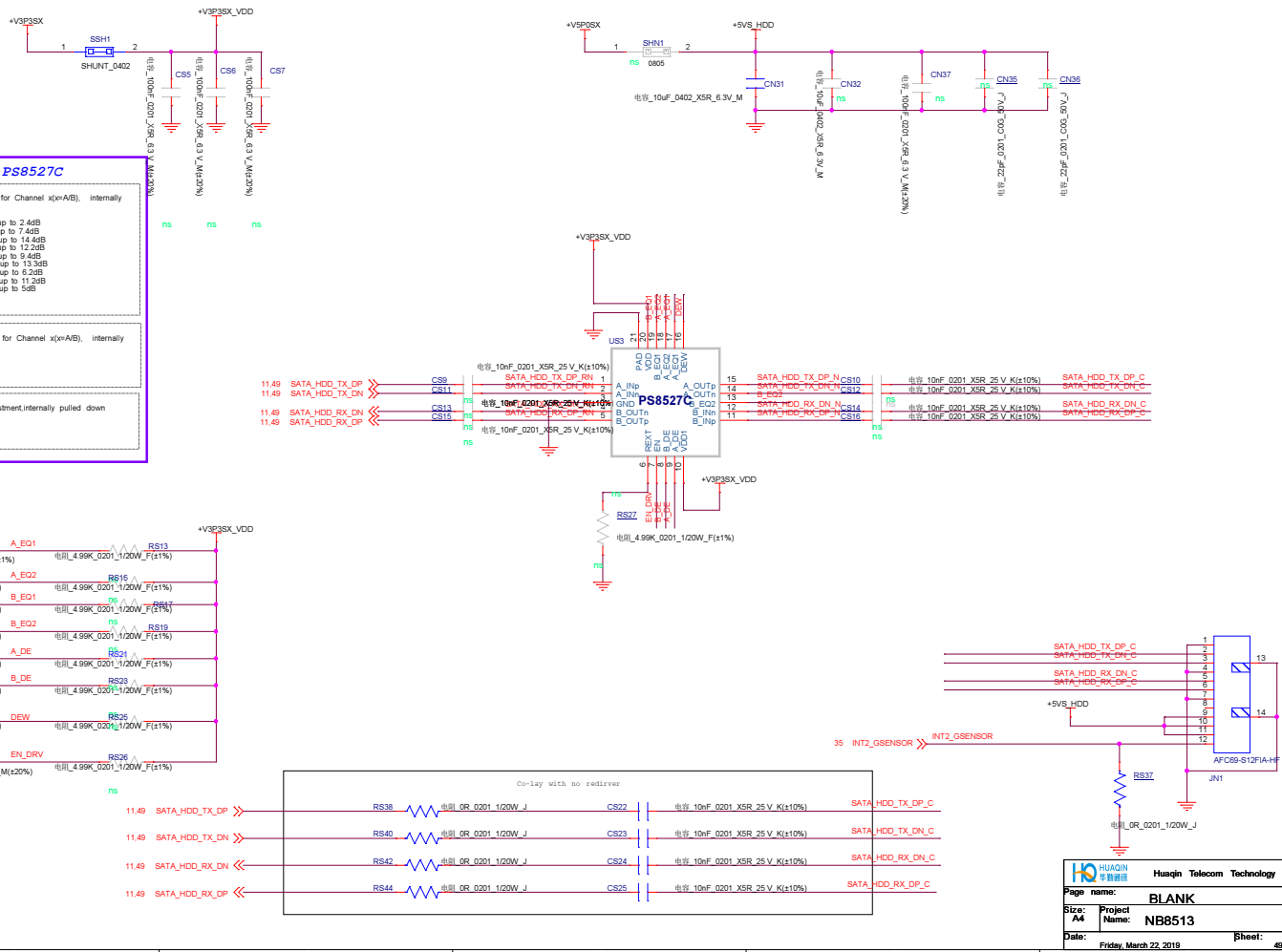
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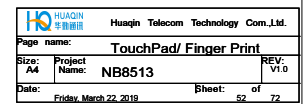
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## Finger Print



~~目前按照同面线定义,待 ME update 同面线~~

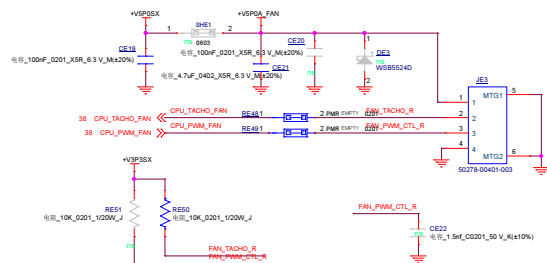
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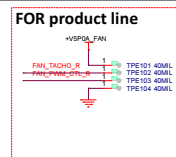
same as N8106 - 01/22

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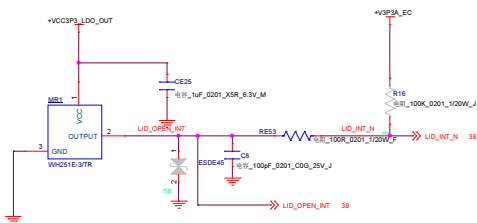




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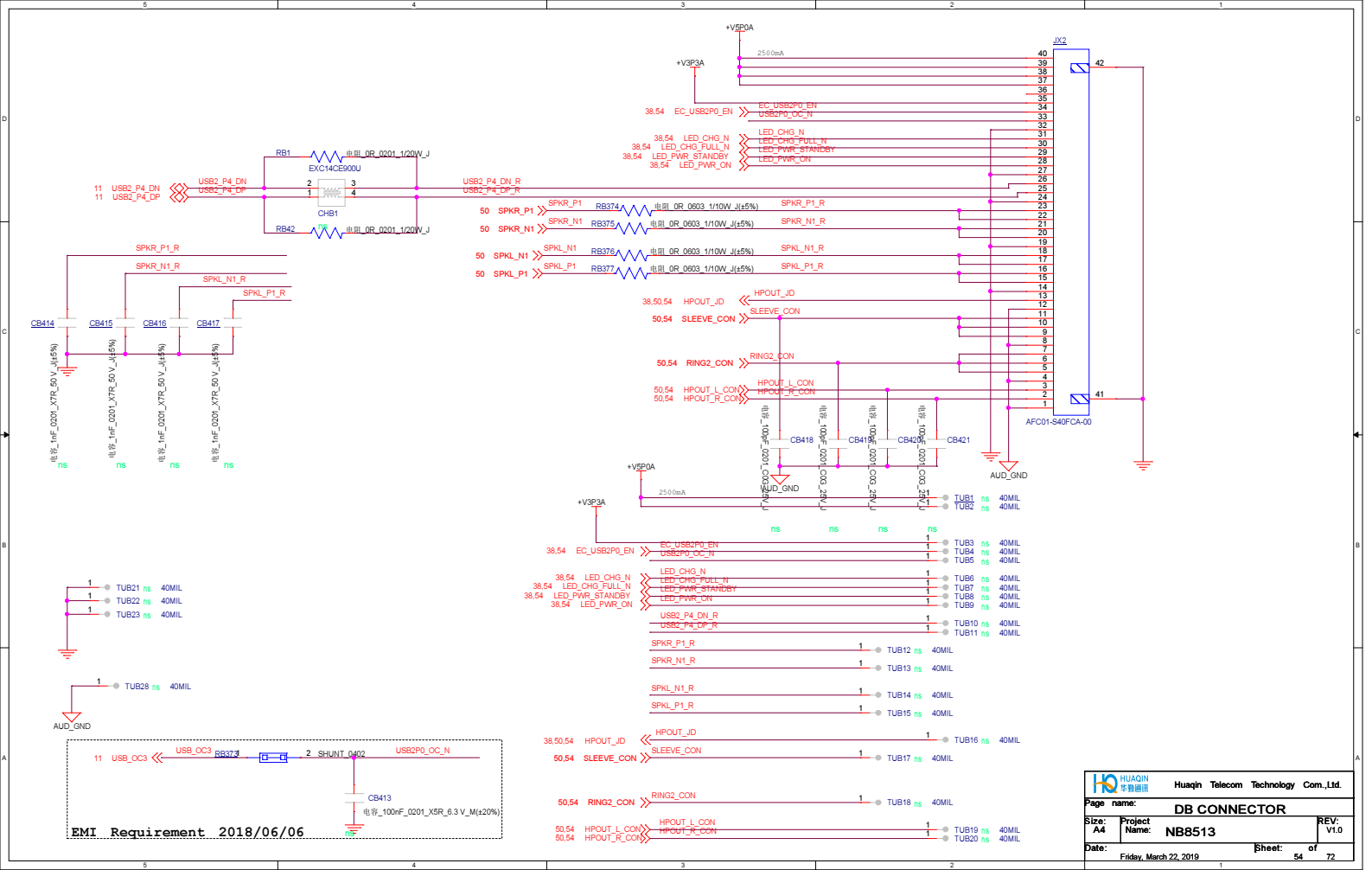


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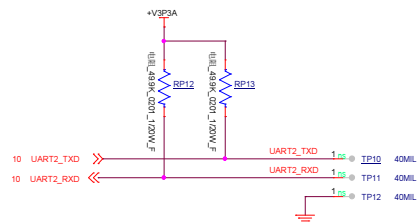
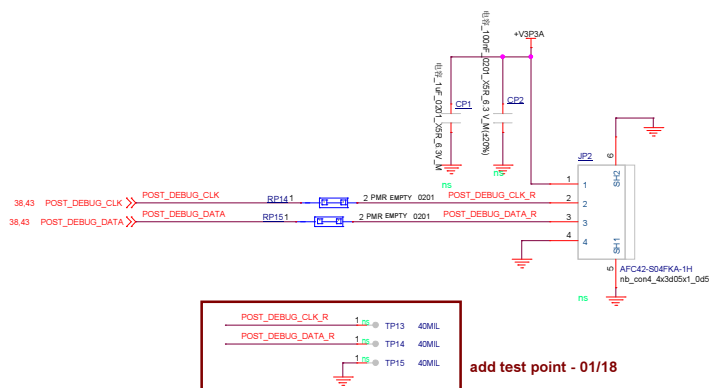


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Size: A4	Project Name: <b>NB8513</b>
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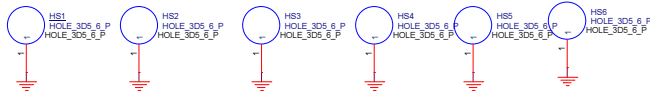




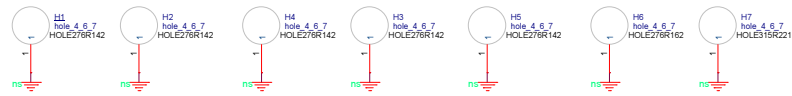


# Need add HQ CODE and Stuff

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Thermal



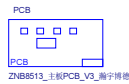
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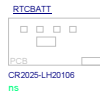
CPU & GPU Boss




WLAN Boss




PCB



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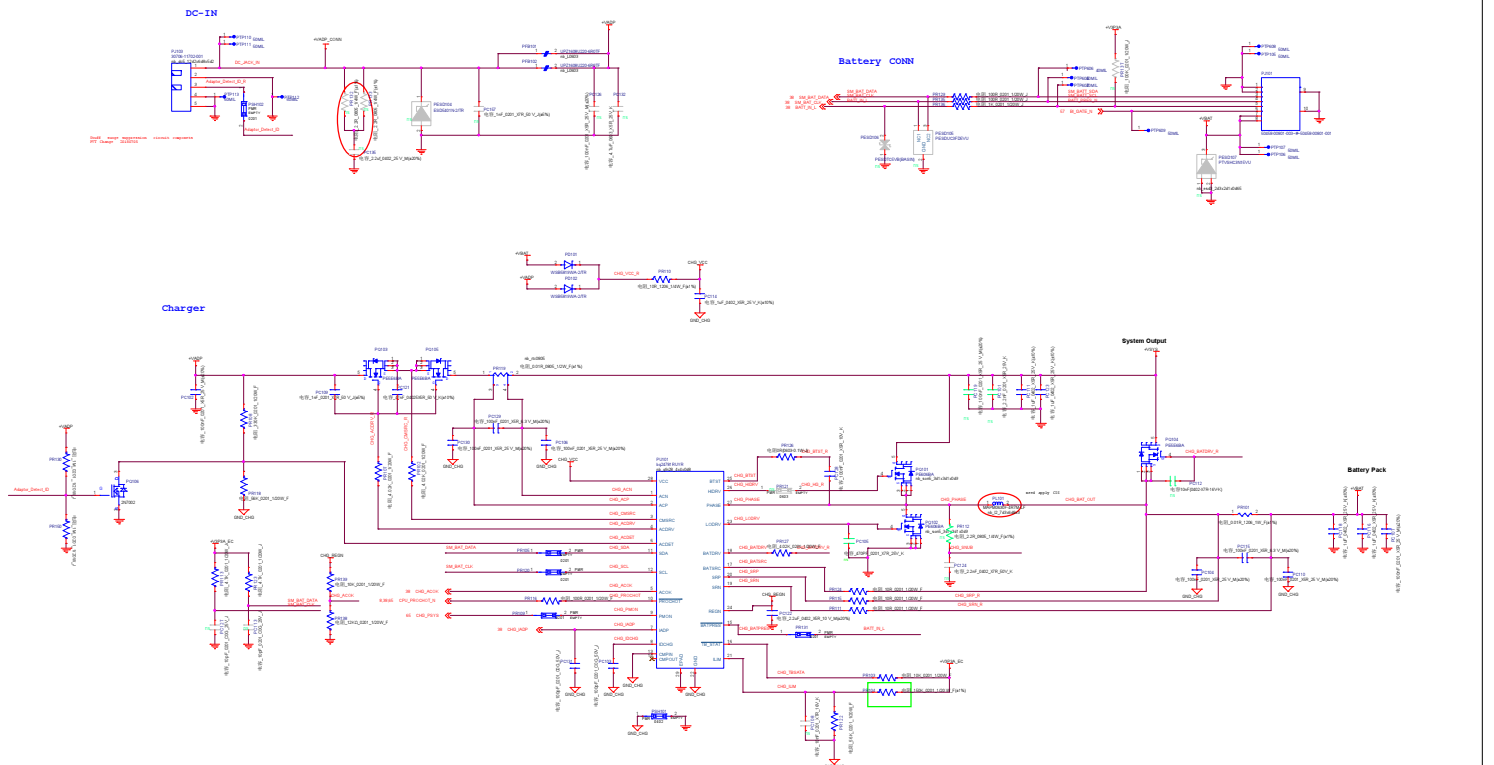
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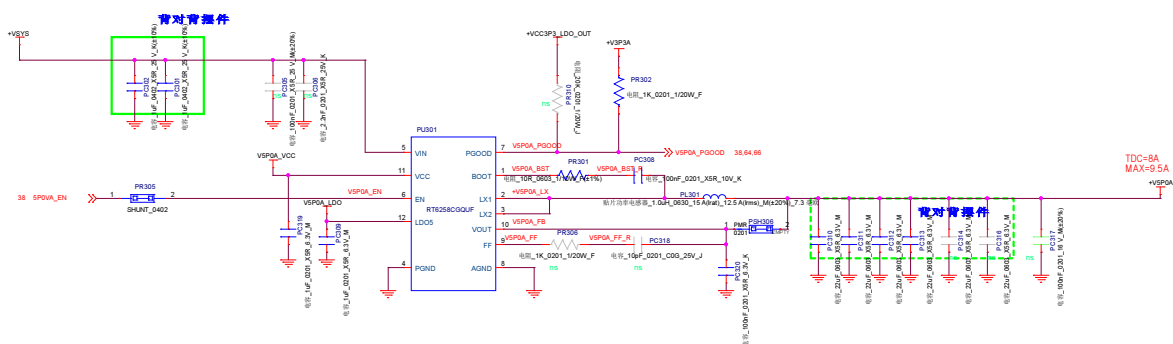













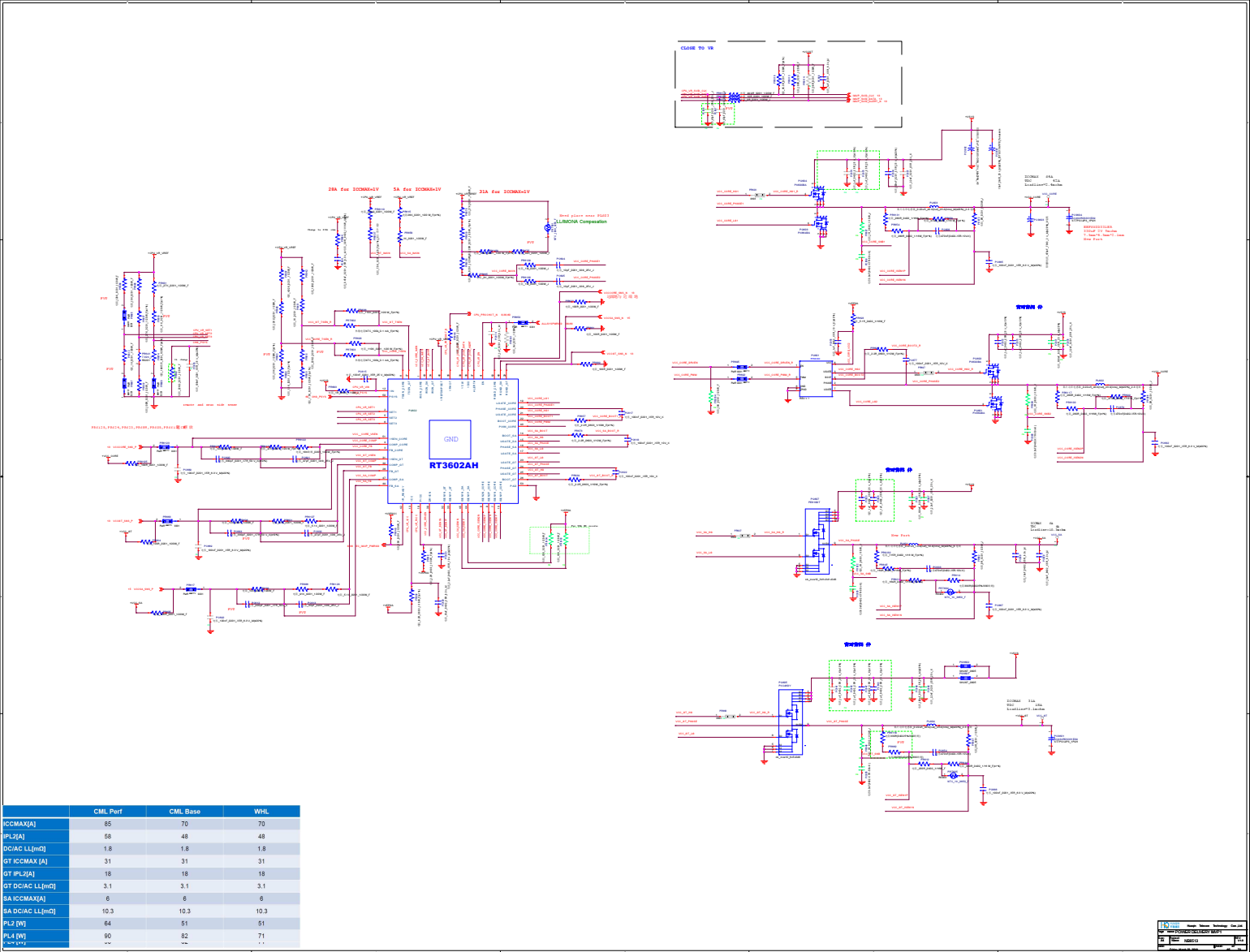


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Size: A4	Project Name: <b>NB8513</b>
Date: <b>Friday, March 22, 2019</b>	REV: <b>V1.0</b>
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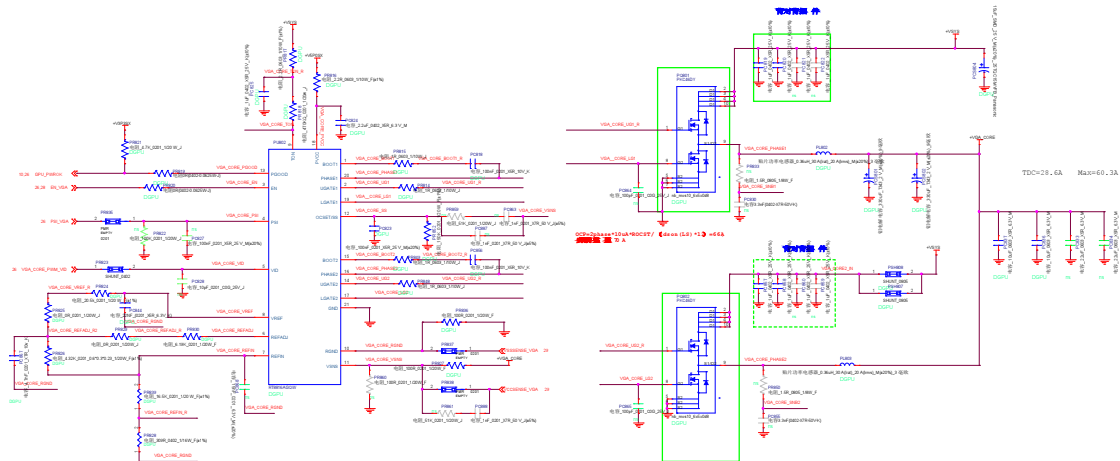


Table 7. Output EDP-Continuous

	NVVDD	GPU FBIO	FB Total <sup>1</sup>	1.0V Total <sup>1</sup>	1.8V Total <sup>2</sup>
Product	(A)	(A)	(A)	(A)	(A)
N175-LG	15.4	2.5	5.0	0.1	0.2
N175-G1	30.0	3.0	5.6	0.1	0.3
N175-G0 <sup>3</sup>	27.8	3.2	5.8	0.2	0.5
N175-G2 <sup>3</sup>	28.6	3.2	5.8	0.2	0.5

Table 8. Output EDP-Peak

	NVVDD	GPU FBIO	FB TOTAL <sup>4</sup>	1.0V Total <sup>1</sup>
Product	(A)	(A)	(A)	(A)
N175-LG	48.3	2.8	5.8	0.2
N175-G1	60.1	3.4	6.9	0.2
N175-G0 <sup>3</sup>	42.0	3.9	7.4	0.3
N175-G2 <sup>3</sup>	60.3	3.9	7.4	0.3



[illegible][illegible]

**G5027RD1D**

Diagram illustrating the connection of the G5027RD1D module to a power supply and a microcontroller.

**Power Supply Connections:**

- +V1P2L\_VDDG** and **+V1P2L\_VDDF** are connected to the module's power pins.
- +V3P3A** and **+V3P3B** are connected to the module's control pins.

**Module Components and Connections:**

- PDS917** (1PDS917) is connected to the module's power pins.
- PDS607C7C1D** (1PDS607C7C1D) is connected to the module's control pins.
- PC858** (1PC858) is connected to the module's control pins.
- VCC5VPR\_OC\_OUT** and **VCC5VPR\_EN** are connected to the module's control pins.
- VBAT5-4WV70** is connected to the module's power pins.
- VBAT5-4WV70** is connected to the module's control pins.
- VBAT5-4WV70** is connected to the module's power pins.
- VBAT5-4WV70** is connected to the module's control pins.

**Microcontroller Connections:**

- VBAT5-4WV70** is connected to the microcontroller's power pins.
- VBAT5-4WV70** is connected to the microcontroller's control pins.
- VBAT5-4WV70** is connected to the microcontroller's power pins.
- VBAT5-4WV70** is connected to the microcontroller's control pins.

								Sx: transitions	
tcPU26	All	CPU	PLT	10	65	us	11	CPU_C10_GATE# de-assertion to VC CSTG stable Note: CPU_C10_GATE# de-assertion to VC CSTG also needs to meet max: 65us on cold boot	
tcPU27	All	CPU	PLT	10	240	us	11	CPU_C10_GATE# de-assertion to VC CIO stable	
tcPU26a	All	CPU	PLT		200	us	36	SLP_S3# assertion to VC CSTG_PWRGD de-assertion	
tcPU28b	All	CPU	PLT	0		us	37, 38	VC CSTG_PWRGD low to VC CSTG	

[illegible]

The schematic diagram shows the PLL circuit for the PLL04 block. The circuit includes a VREGSA supply, a 38.86 MHz ALLSYSPWRO input, a PR021 oscillator, a PLL04 block, and a VREGSA output. Key components include a 100nF capacitor, a 100pF capacitor, a 100k resistor, and a 100pF capacitor. The PLL04 block has pins for VIN1, VIN2, VOUT1, VOUT2, CT, VBIAS, and GND. The output is connected to a VREGSA supply and a 100nF capacitor.

[illegible]







### 背对背摆件



ILMT=Low	6.7	7.8	8.9	A
ILMT=Floating	9.3	10.6	11.9	A
ILMT=High	12	13.3	14.8	A

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